

UHV Training 22-24 October 2019

Vacuum technology for synchrotron light sources

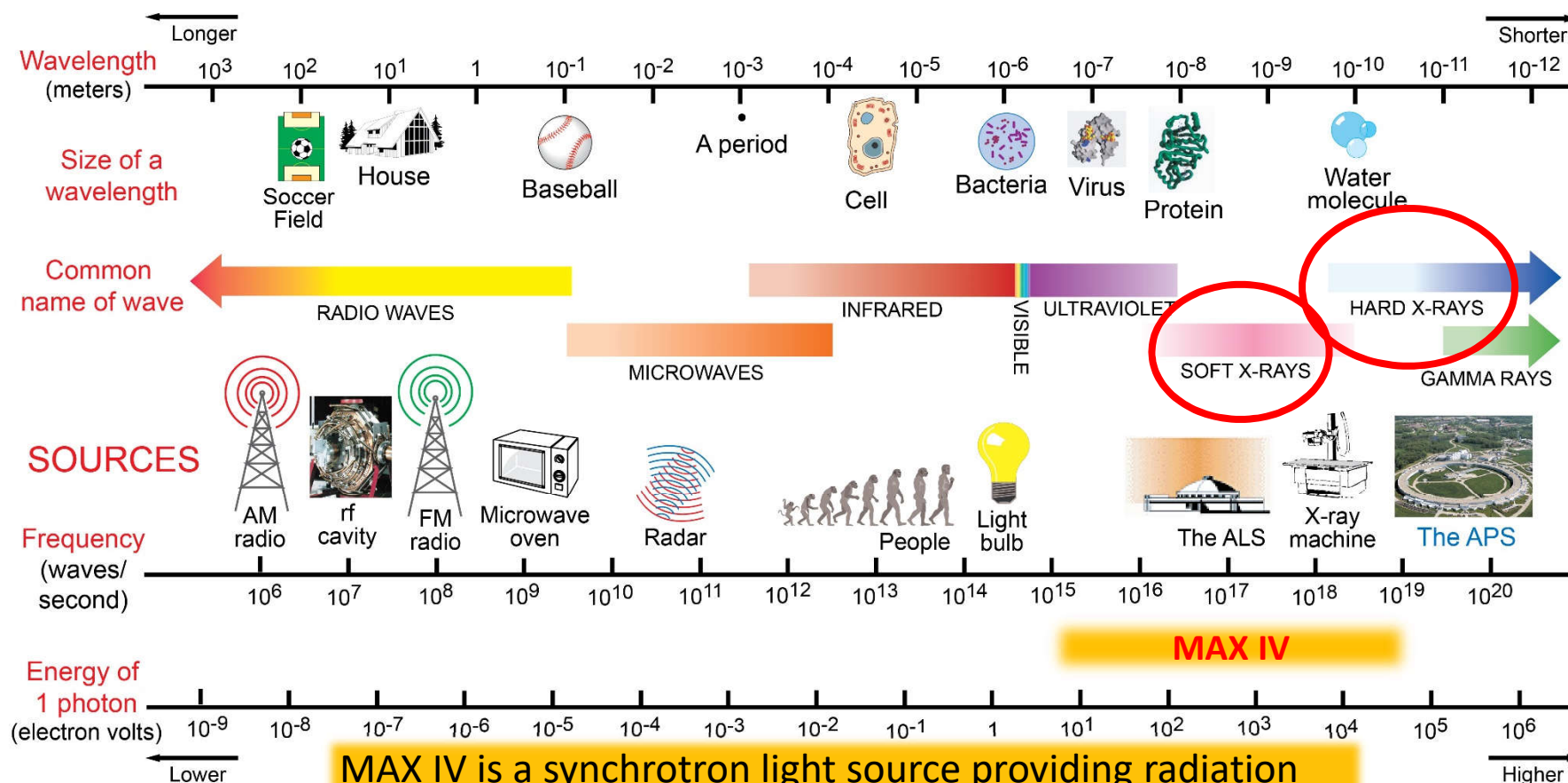
23rd October 2019, ESS, Lund

- What is a synchrotron light source?
- Why we need vacuum in particle accelerator?
- Basics of vacuum (for particle accelerators),
- Sources of gas,
- Vacuum pumps and sensors,
- MAXIV 3 GeV storage ring layout, design and installation,
- MAXIV 1.5 GeV storage ring layout and design.

What is MAX IV?

MAX IV - set of particle accelerators producing electromagnetic radiation (synchrotron light) which is used at beamlines for experiments and measurements.

THE ELECTROMAGNETIC SPECTRUM

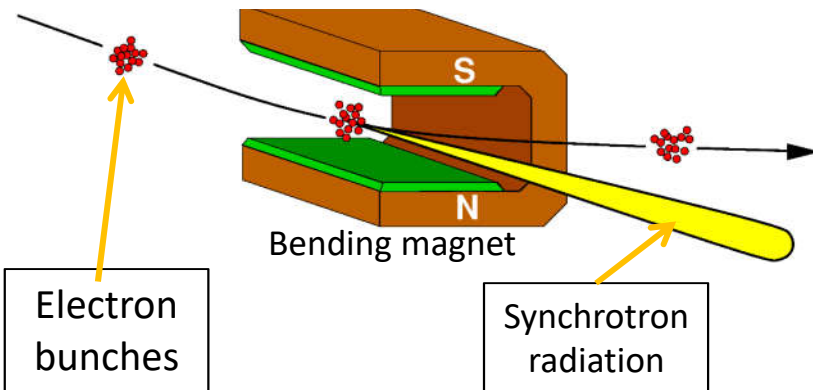
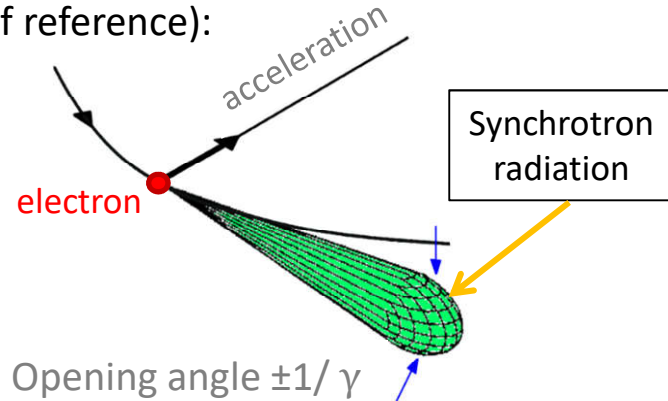


MAX IV is a synchrotron light source providing radiation from 4 eV till 40 keV to the beamlines for experiments.

www2.lbl.gov

How light is generated

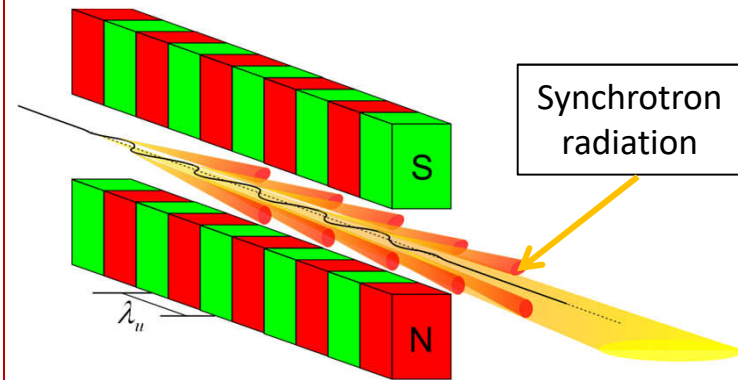
Radiation emission of a relativistic electron (stationary lab frame of reference):



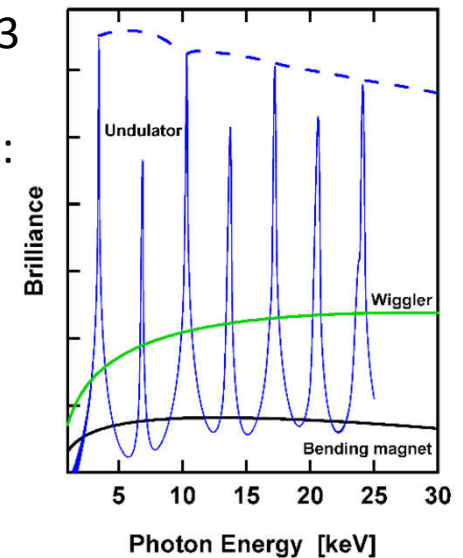
$$\text{brilliance} = \frac{\# \text{photons}}{s \cdot \text{mrad}^2 \cdot \text{mm}^2 \cdot 0,1\% BW}$$

The greater the brilliance, the more photons of a given wavelength and direction are concentrated on a spot per unit of time.
Brilliance is mainly determined by the cross-section of the electron beam.

Insertion device - periodic magnetic structure (wiggler, undulator):



Brilliance of 3 radiation source types:



4th Generation light source

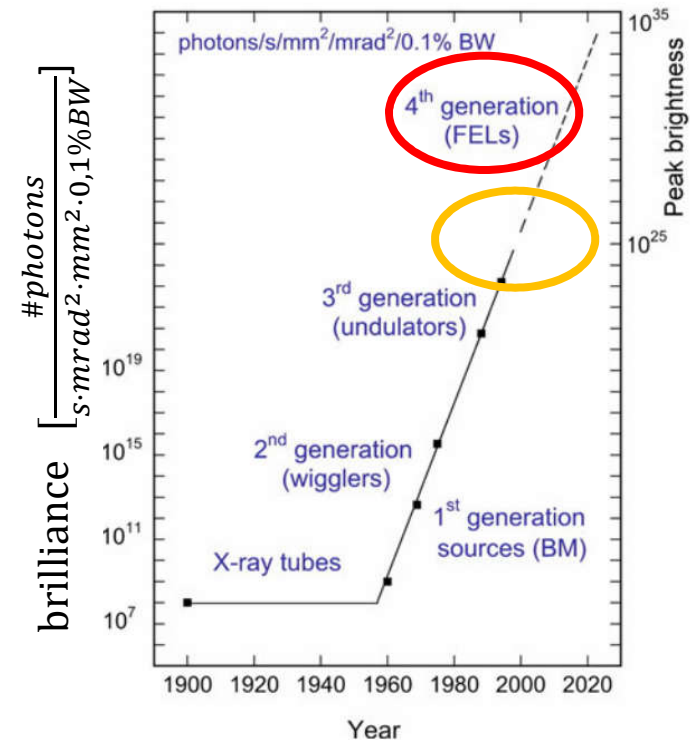
4th Generation light sources, mainly Free Electron Lasers (FELs) with brilliance higher from previous generation by many orders of magnitude.

MAX IV is **storage ring based** 4th generation light source with brilliance higher by at least one order of magnitude from 3rd generation light sources.

At MAX IV:

- Higher brilliance is achieved by lowering electron beam emittance,
- Only insertion devices are used: wigglers, undulators (no more bending magnet radiation).

X-ray source brilliance as a function of time since discovery of X-rays in 1895

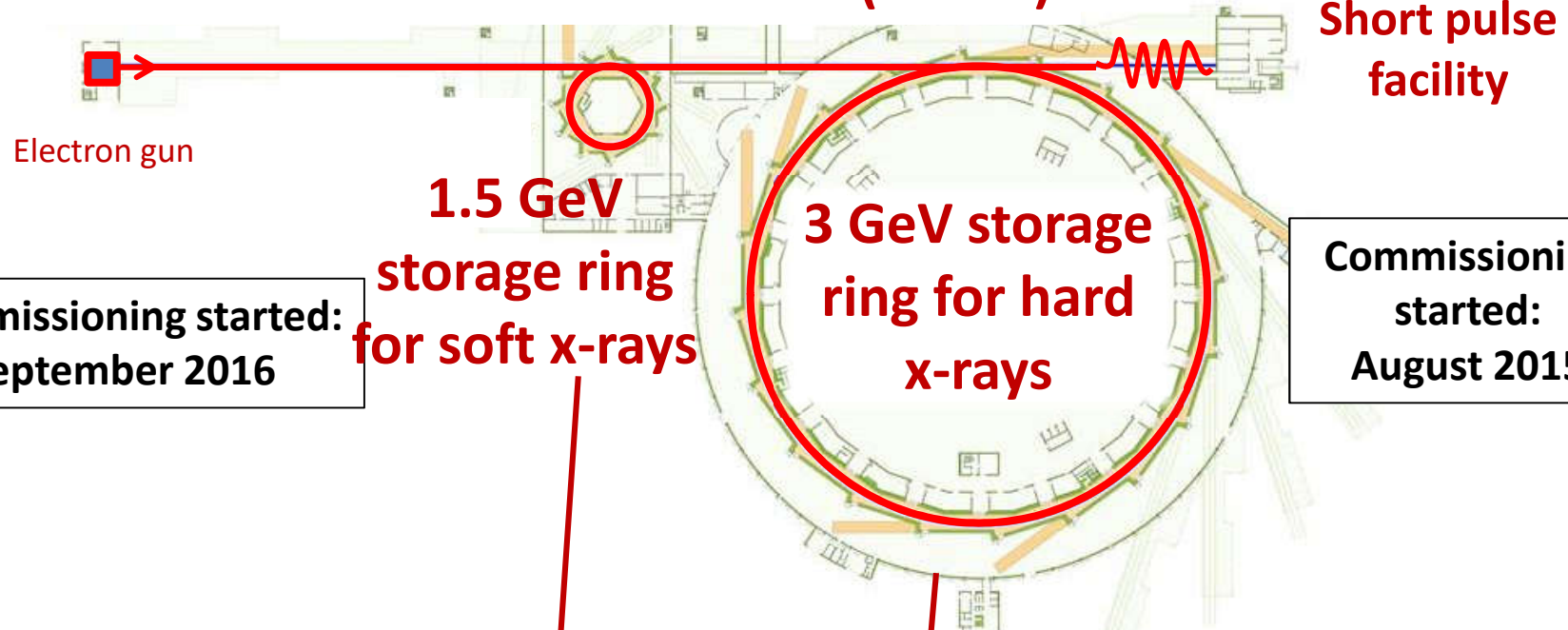


4th generation light sources:
at least 1 important parameter factor of 10 better than the previous generation.

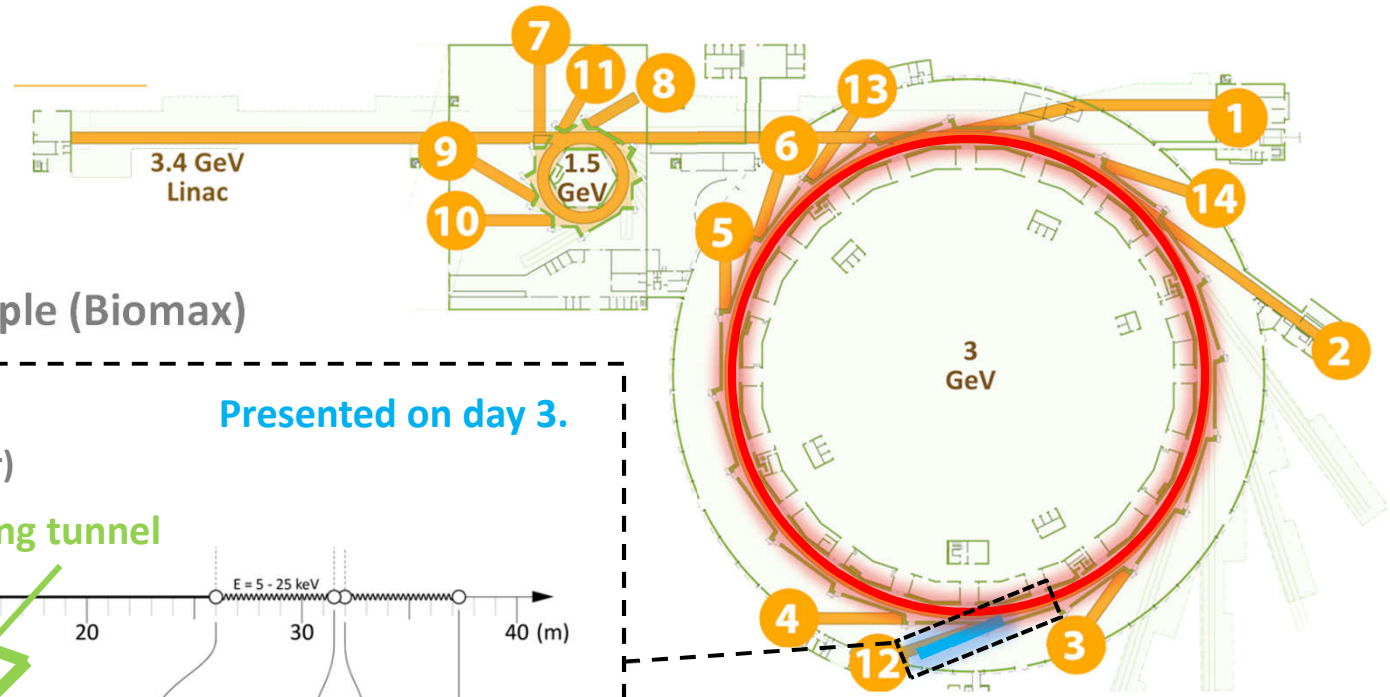
MAX IV layout

Synchrotron light source facility in Lund, Sweden.

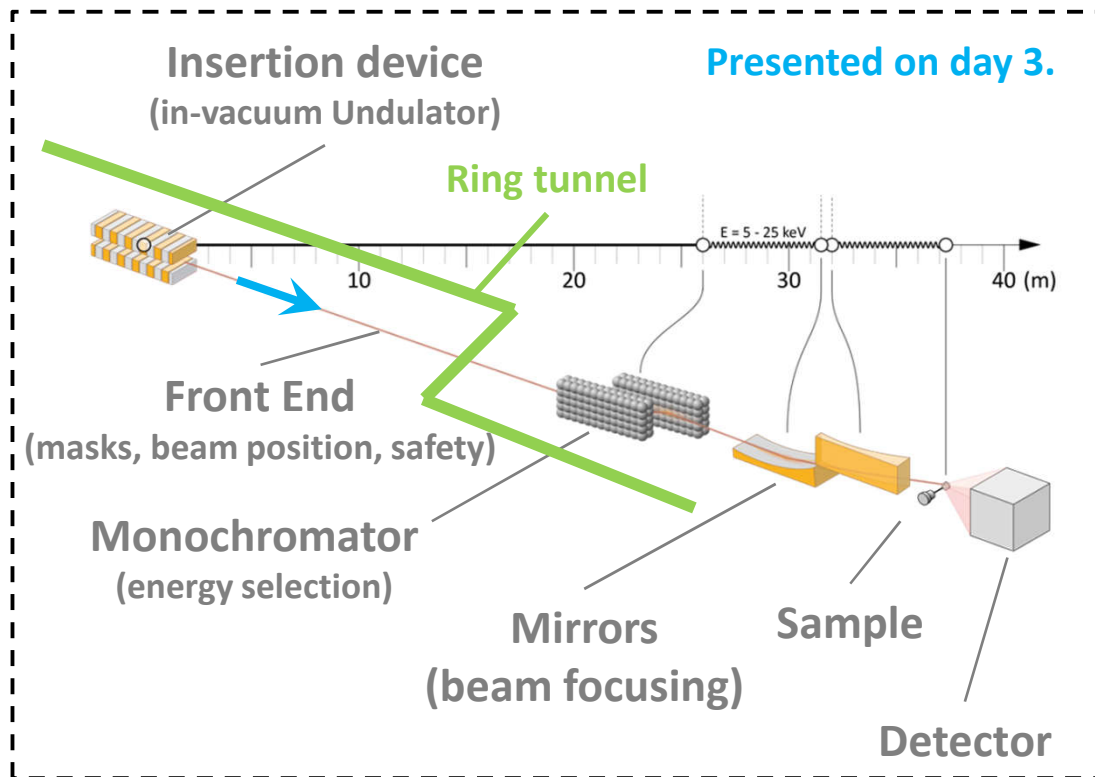
3.4 GeV Linear accelerator - Linac (300 m)



MAX IV beamline layout



Beamline layout example (Biomax)



Beamlines at MAX IV:
11 beamlines in operation/commissioning,
3 being installed,
2 under design.

Total beamline capacity: ~30 beamlines

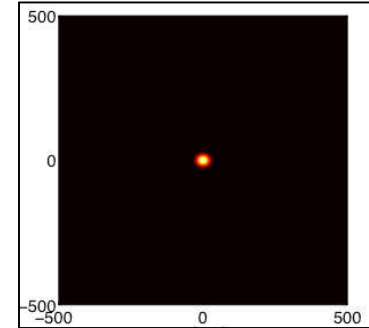
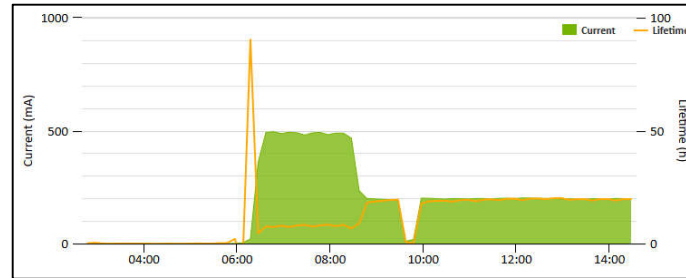
<https://www.maxiv.lu.se/>

Why we need vacuum in particle accelerators?

Why do we need vacuum in particle accelerator?

Less beam-gas interaction:

- Increase beam **lifetime**,
- Prevents to increase beam size,
- Reduces radiation hazard,
- Allows the synchrotron radiation (light) reach the sample,
- Helps to protect optics...



OLAV IV 2014, Matthew Cox

Why do we need vacuum in particle accelerator?

The total beam **lifetime** in a particle accelerator is given by:

$$\frac{1}{\tau} = \frac{1}{\tau_{elastic}} + \frac{1}{\tau_{inelastic}} + \frac{1}{\tau_{Touschek}} + \frac{1}{\tau_{quantum}}$$

The interaction between beam particles and residual gas molecules consist of two main mechanisms: elastic and inelastic scattering which contribute to total beam lifetime.

Elastic, inelastic beam lifetime:

$$\tau_{el,inel} \sim \frac{1}{Z^2} \frac{1}{n_g}$$

Z - atomic number of the residual gas
(depends on gas specie),

n_g - residual gas density (pressure).

Not only the absolute pressure is important but also what are the gas species in the system

Basics of vacuum (for particle accelerators)

Pressure units

Conversion table: units of pressure

	Pa	bar	atm	Torr
1 Pa	1	10^{-5}	$9.87 \cdot 10^{-6}$	$7.5 \cdot 10^{-3}$
1 bar	10^2	1	0.987	750.06
1 atm	$1.013 \cdot 10^5$	1.013	1	760
1 Torr	133.32	$1.33 \cdot 10^{-3}$	$1.32 \cdot 10^{-3}$	1

In vacuum technology: mbar or Pa

Vacuum ranges

1 Atm. = 1013 mbar \approx 1 bar

	Pressure range [mbar]
Low Vacuum	$10^3 - 1$
Medium Vacuum	$1 - 10^{-3}$
High Vacuum (HV)	$10^{-3} - 10^{-9}$
Ultra High Vacuum (UHV)	$10^{-9} - 10^{-12}$
Extreme High Vacuum XHV	$< 10^{-12}$

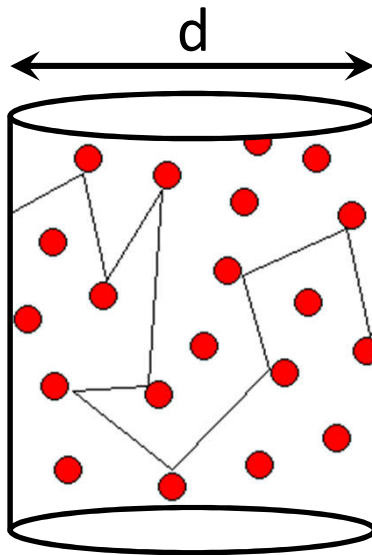
Storage rings,
Beamlines



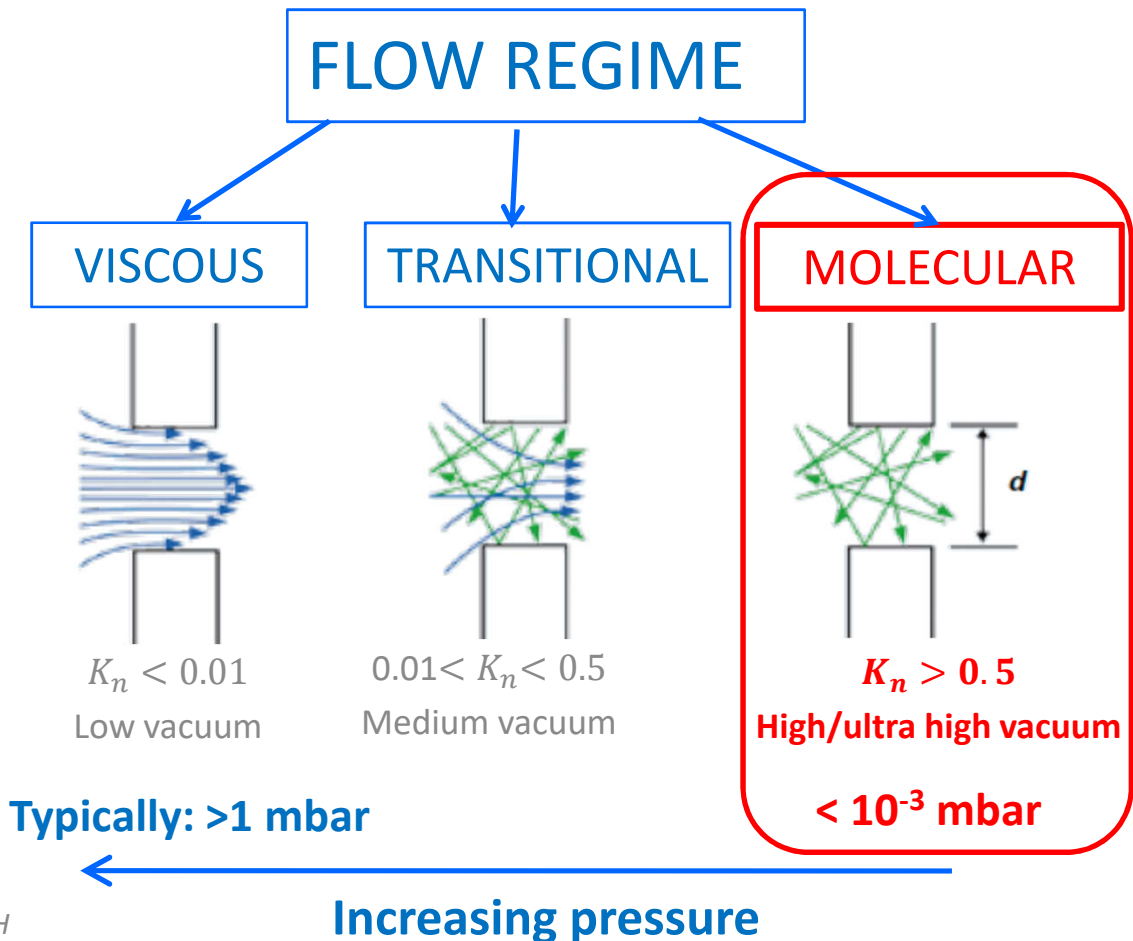
Flow regimes

$$K_n = \frac{l}{d}$$

- l - Mean free path [m]
 d - Diameter of flow channel [m]
 K_n - Knudsen number [dimensionless]



Mean free path:
 At atm. Pressure = 6.5×10^{-8} m
 At 10^{-9} mbar (storage ring) = 66 km

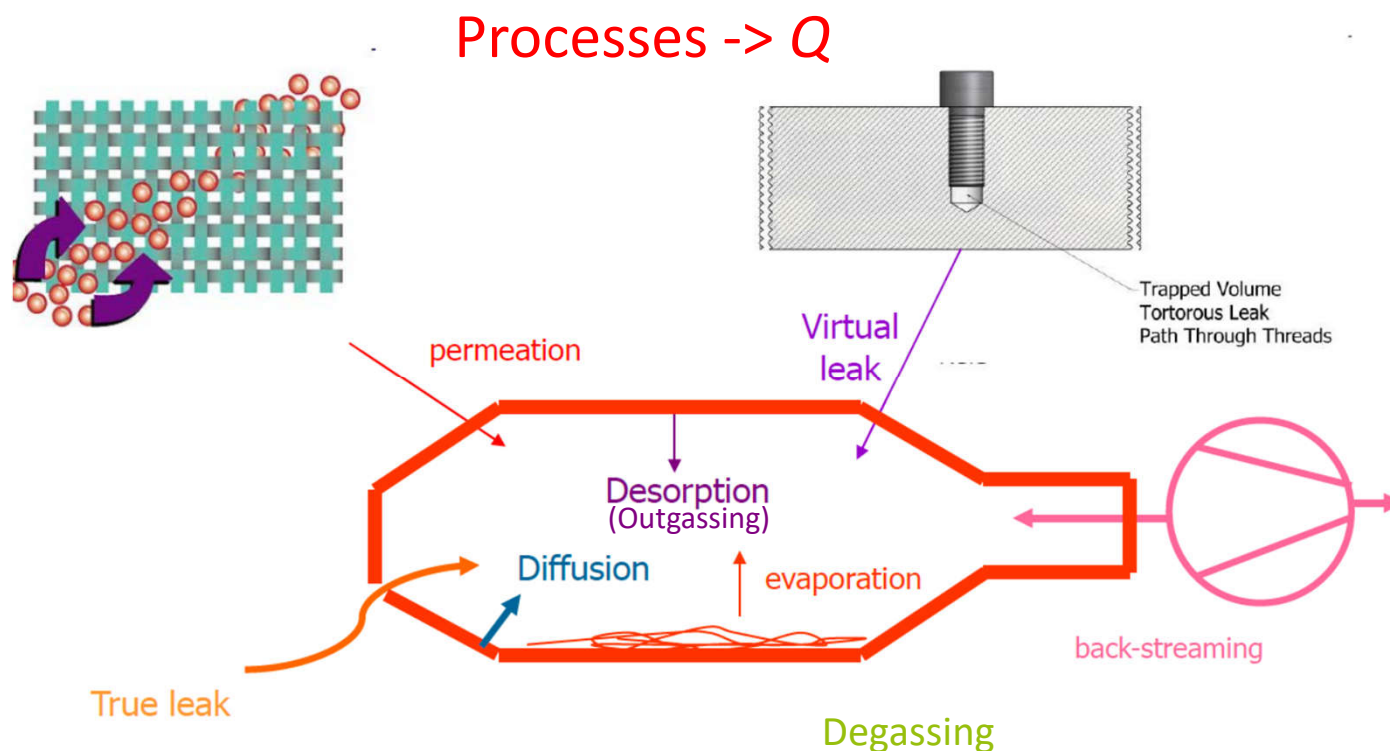


Vacuum Technology Know how by Pfeiffer Vacuum GmbH

Sources of gas

Sources of gases

Sources of static gas loads in vacuum system:

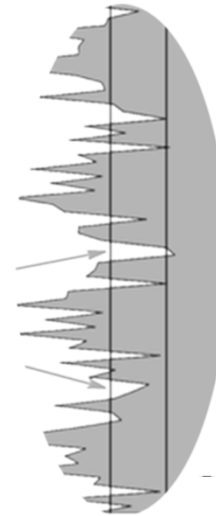
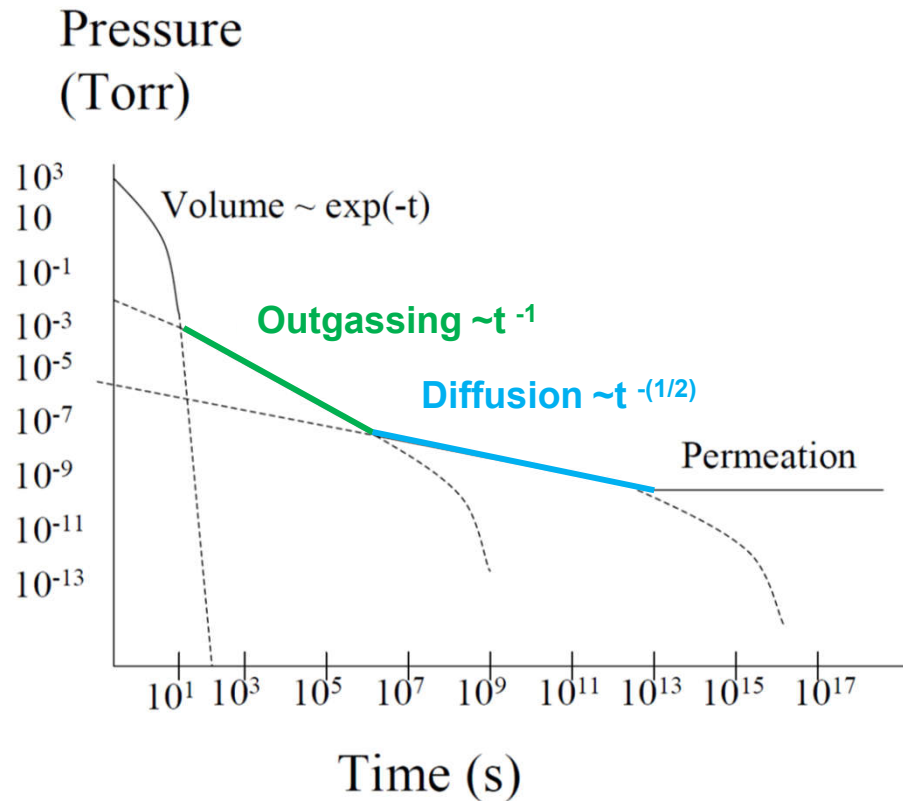


Vacuum chambers are sources of gas

Courtesy of Eshraq Al-Dmour

What process defines pressure

What process defines the pressure over time?



Outgassing:

Material

– Binding energy

Surface condition

– As delivered

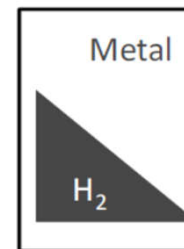
– Machined

– Polished

– Cleaning

– Heat treatment

Presented
on day 3.



Vacuum

Difussion:

- Material

- Heat treatment

(Vacuum firing)

- Inner surface barrier

(Air baking, Film deposition)

<http://web.utk.edu/~prack/Thin%20films/VACUUM-3.pdf>

Thermal outgassing (static outgassing)

For metals:

- If not **baked** (not heated) in-situ **water** is the dominant gas specie.
- If **baked** (heated above ~120°C in vacuum) in-situ **hydrogen** H₂ is the dominant gas

$$q_{H_2O} \approx \frac{3 \times 10^{-9}}{t[h]} \left[\frac{\text{mbar l}}{\text{s cm}^2} \right]$$

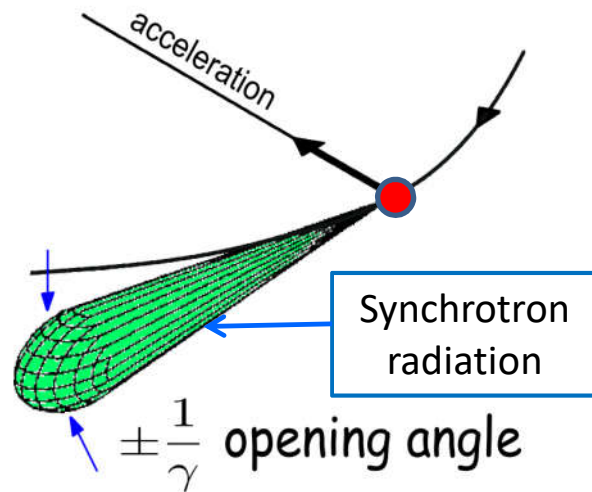
Outgassing rates $q \left[\frac{\text{torr l}}{\text{s cm}^2} \right]$ at 20°C:

Austenitic stainless steel not baked, after 10 h pumping	3x10 ⁻¹⁰ (main gas: H ₂ O)
Austenitic stainless steel baked in-situ for 24 h at 150°C	2x10 ⁻¹² (main gas: H ₂)
OFS copper baked in-situ for 24 h at 200°C	~10 ⁻¹⁴ (main gas: H ₂)

Polymers (Viton, PEEK, Kapton) have high **water vapour solubility**, therefore have **much higher outgassing rates** than metals.

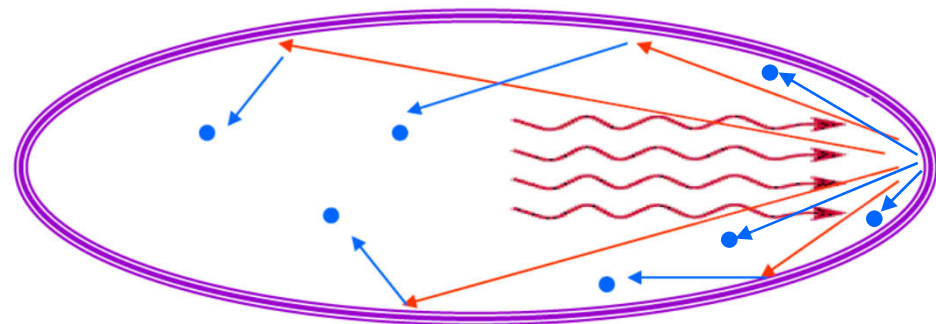
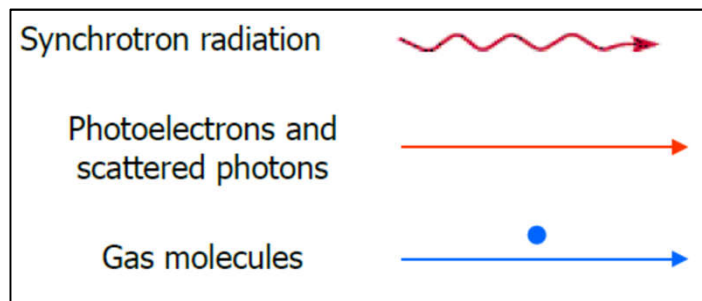
Dynamic outgassing

In particle accelerators energized particles impinging on vacuum surfaces induce desorption of molecules. Usually such dynamic gas load dominate over thermal outgassing.



Photon Stimulated Desorption

When charged particles (moving at relativistic speeds) are accelerated they emit synchrotron radiation in a narrow cone. This photon flux impinging on vacuum surfaces produces strong outgassing thus a large dynamic pressure increase.



http://photon-science.desy.de/research/studentsteaching/primers/synchrotron_radiation/index_eng.html

Courtesy of Eshraq Al-Dmour

Dynamic outgassing

Beam stimulated desorption is characterised by η - the **desorption yield**:

$$\eta = \frac{\text{number of desorbed molecules}}{\text{number of particle impinging the surface}}$$

η – depends on many parameters:

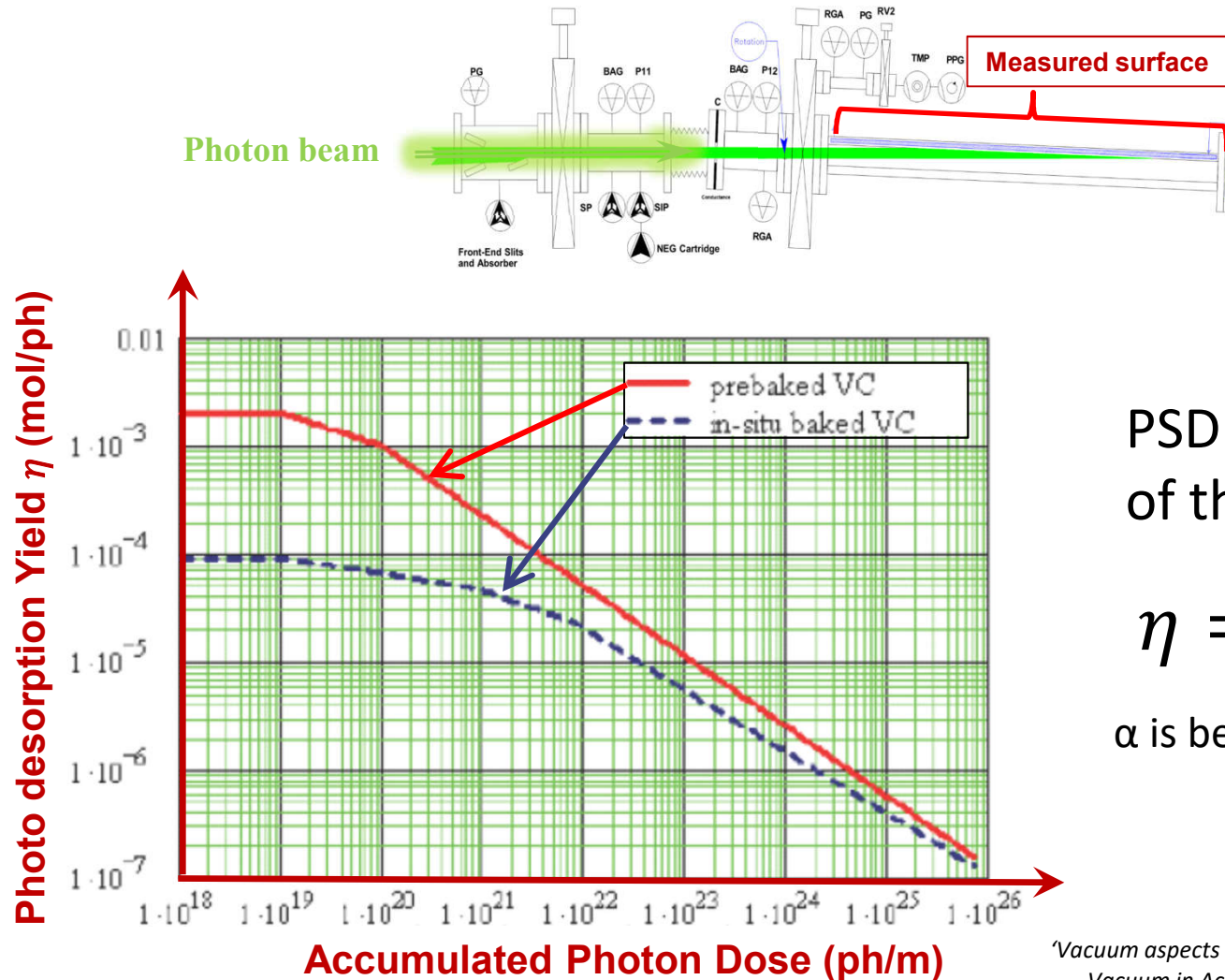
- incident particle: type, angle and energy,
- material,
- surface roughness,
- **cleanliness** of the surface,
- history of the material (dose),
- Particle flux.

The desorption may be stimulated by:

- electrons,
- ions,
- **synchrotron radiation (photons).**

Photon Stimulated Desorption

Evaluating Photon Stimulated Desorption (PSD):



PSD yield effect
of the dose:

$$\eta = \eta_0 D^{-\alpha}$$

α is between 0.6 and ~ 1

*'Vacuum aspects of synchrotron light sources', R. Reid,
Vacuum in Accelerators, CAS 2006 proceedings*

Vacuum scrubbing

3 GeV ring vacuum conditioning:

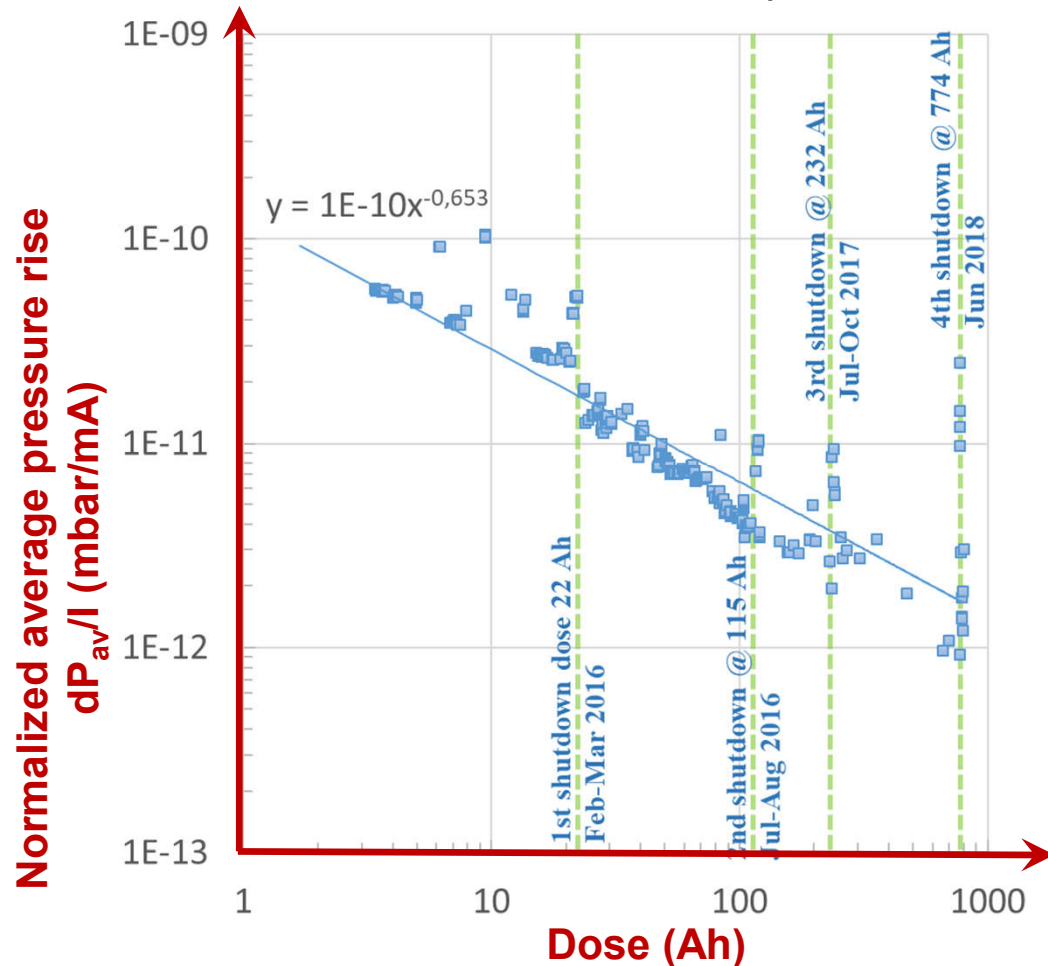
Average pressure normalized to machine current
vs accumulated beam dose (or photon dose)

Dynamic pressure is
proportional to current:

$$P \propto I$$

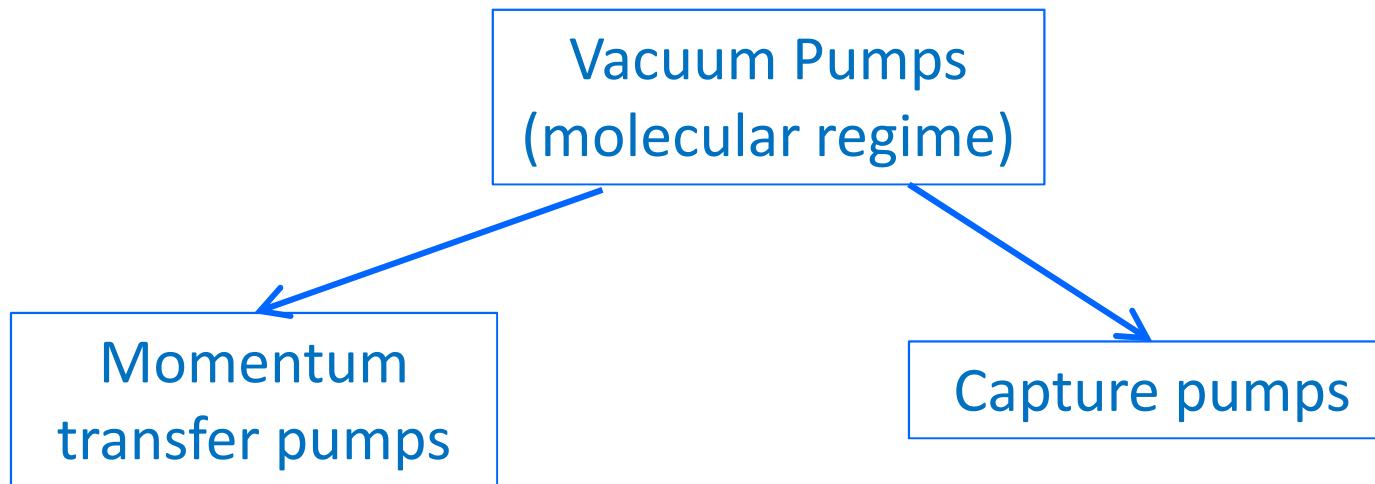
Dynamic pressure rise:

$$\frac{\Delta P}{I}$$



Vacuum pumps and sensors

Pump clasification



Example: Turbomolecular Pump

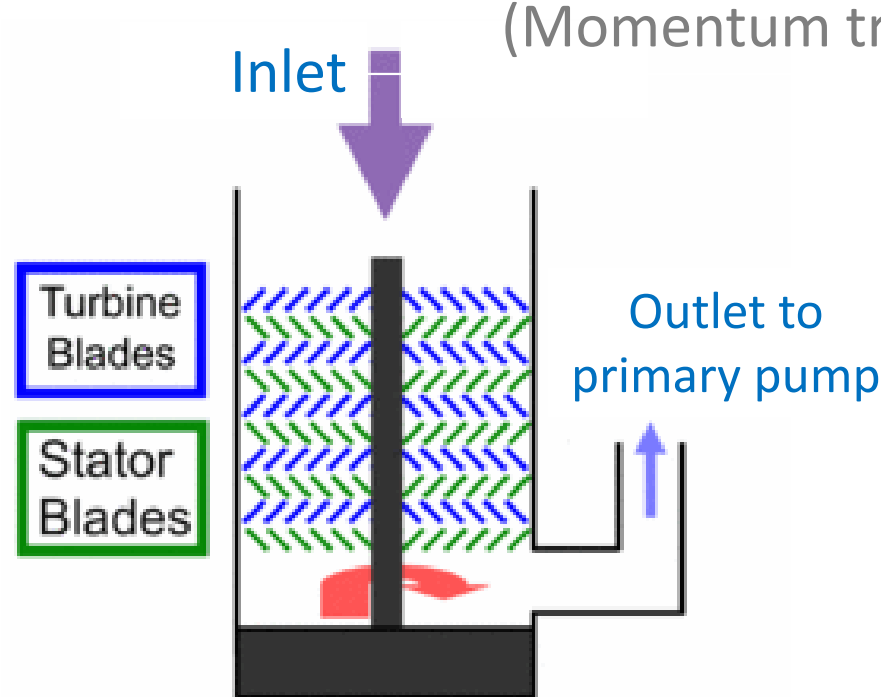
Principle: Molecules impinge on fast moving surfaces which direct them towards the pump outlet where they are evacuated by pumps operating in viscous flow. The molecules do not transfer energy to each other.

Example: Sputter Ion Pump, Getter pump, Cryo pump

Principle: gas molecules are fixed to a surface inside vacuum (pump has no moving parts).

Turbomolecular Pump

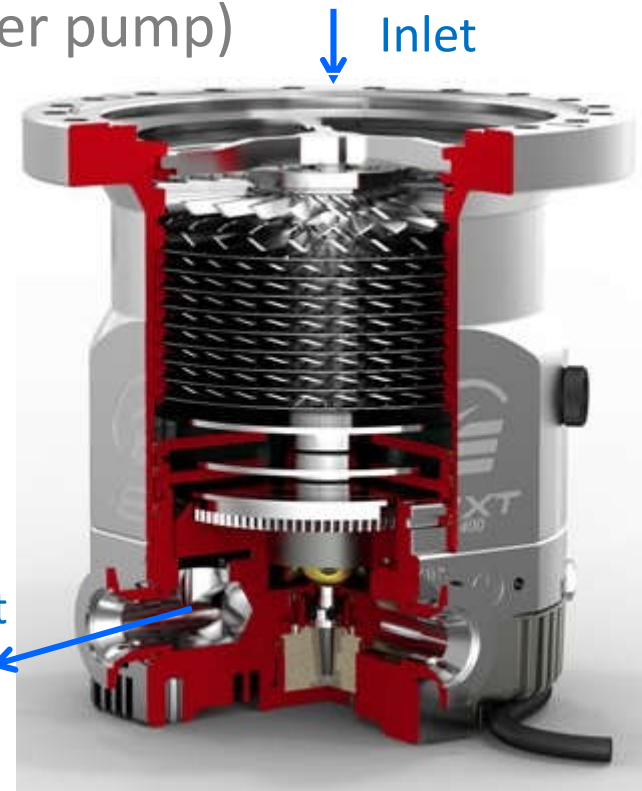
(Momentum transfer pump)



Blade rotational speed 1000 – 1500 Hz

Pressure range: 10^{-1} till 10^{-10} mbar,
(with backing pump connected in series).
Usual operational pressure $< 10^{-5}$ mbar.

'Fundamentals of vacuum technology' (Leybold)



S (pumping speed) does not depend significantly on the mass of the molecule.

$K_o = \frac{P_{outlet}}{P_{inlet}}$ (**compression ratio**) depends exponentially on the wall speed and square root of the gas molecule mass.

Turbomolecular Pumping station



Turbo molecular and roughing pump connected in series can pump from 1 bar (atmospheric pressure) until $\sim 10^{-10}$ mbar

Turbomolecular Pump (range: 10^{-1} to 10^{-10} mbar)

Connection from turbo to primary pump

Primary pump (operating range: 1 bar to 3×10^{-2} mbar)

Turbomolecular in series with primary pumps are widely used in particle accelerators to:

- evacuate vacuum systems from atmospheric to ultra high vacuum,
- Test (leak tests),
- Condition (bakeouts),
- High gas loads.

For accelerator operation with beam capture pumps take over,

Usually they are not permanent part of the vacuum system (attached when needed).

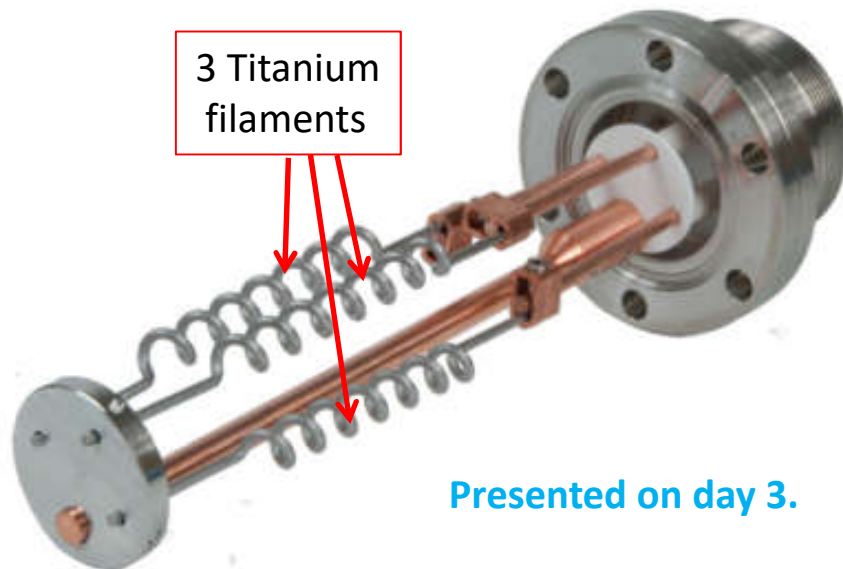
May be used for high gas loads at beamlines.

Presented on day 3.

Capture pumps: getters

Getter materials adsorb gas molecules on their surface which is contamination and native oxide layer free. Such surface can be produced in two ways:

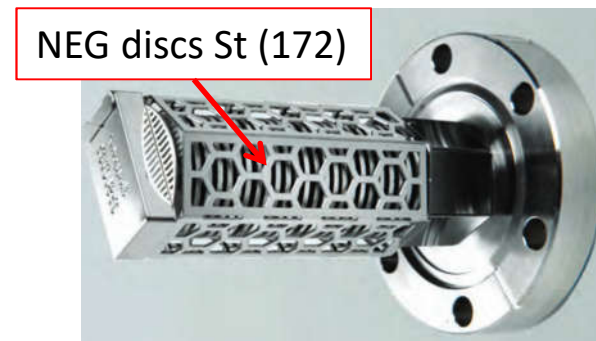
Sublimating (evaporating) at ~ 1500 deg C the reactive metal (Titanium) *in situ*: **evaporable getters** or **sublimation pumps**,



Frequent sublimation needed as the reactive layer is thin and nonporous.

Getter materials do not pump **noble gases** and **methane (CH_4)** at room temperature. Therefore, they need auxiliary pumping to keep a stable pressure.

Dissolving the surface contamination into the bulk of the getter material by heating: **non-evaporable getters (NEG)**; the dissolution process is called **activation**.

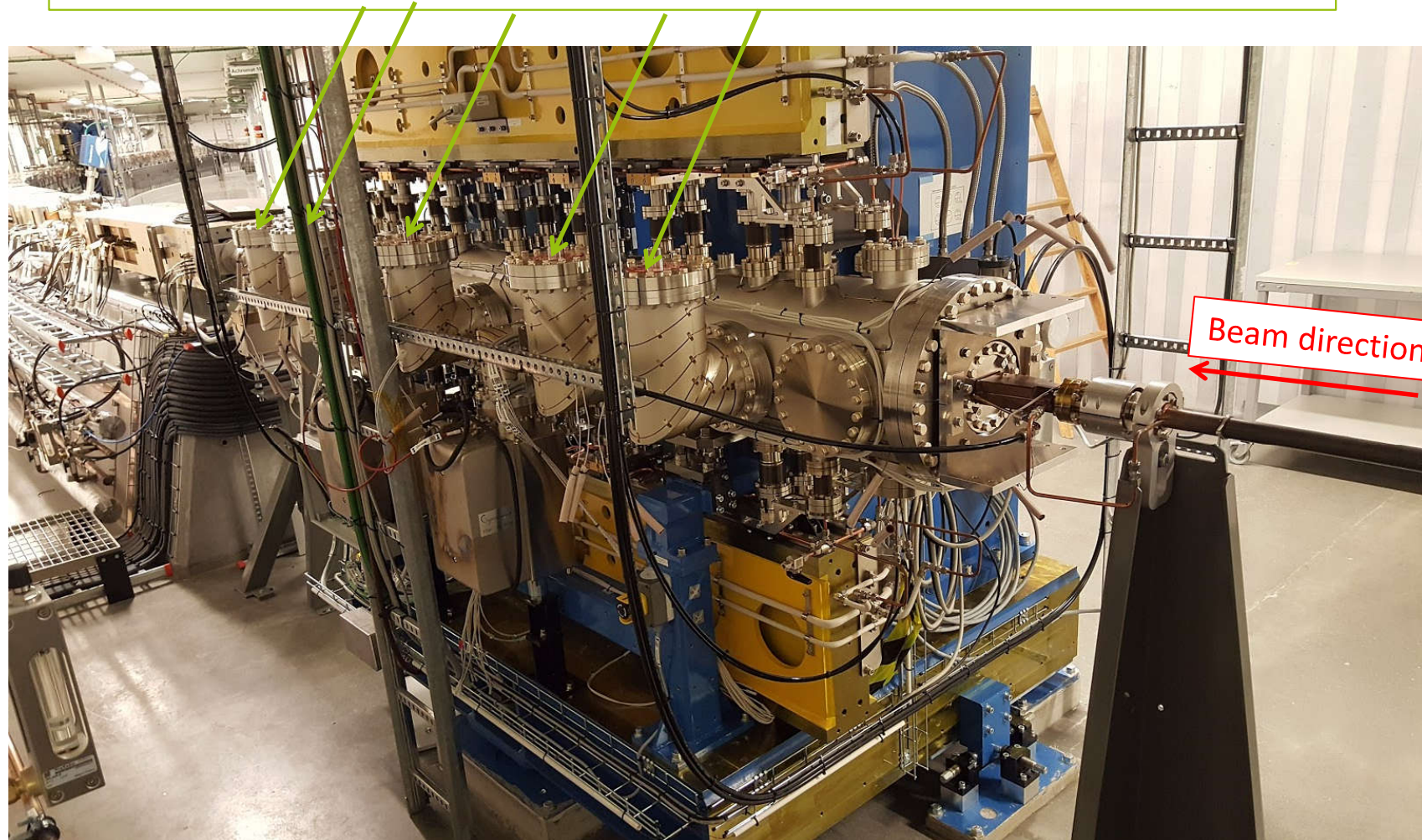


Full pumping speed obtained after heating at 450°C for 45 minutes.

Pump high quantities of gas without reactivation (cartridges are porous). After 40 venting cycles (with nitrogen) and reactivation 80% pumping speed is conserved.

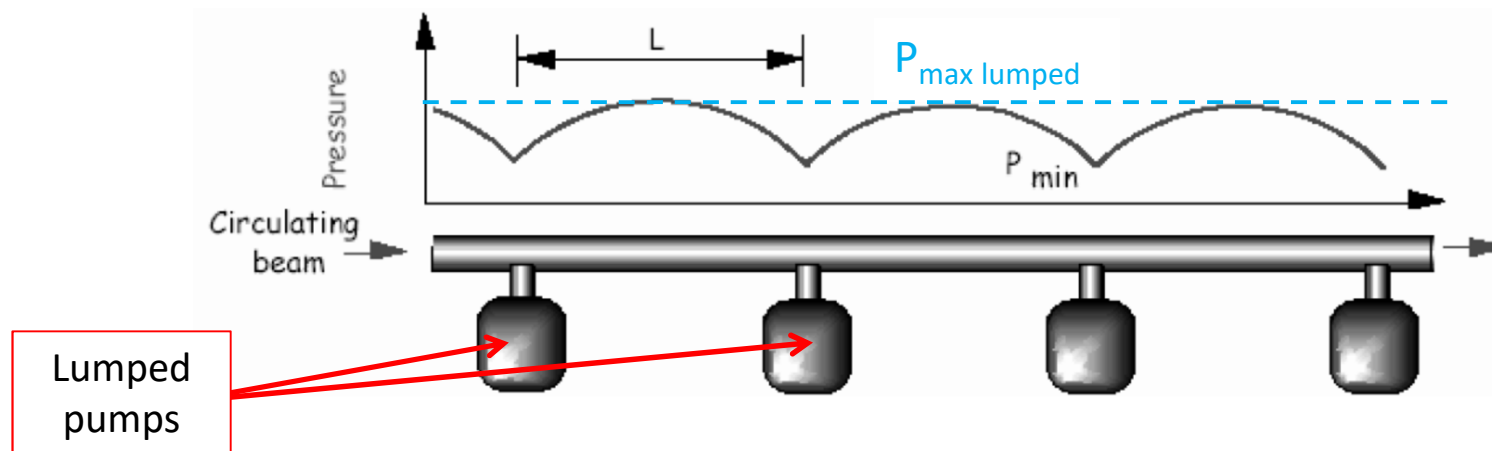
Non-Evaporable Getters (NEG)

5 NEG pumps mounted on COSAXS Insertion Device (In-vacuum Undulator) inside 3 GeV storage ring.

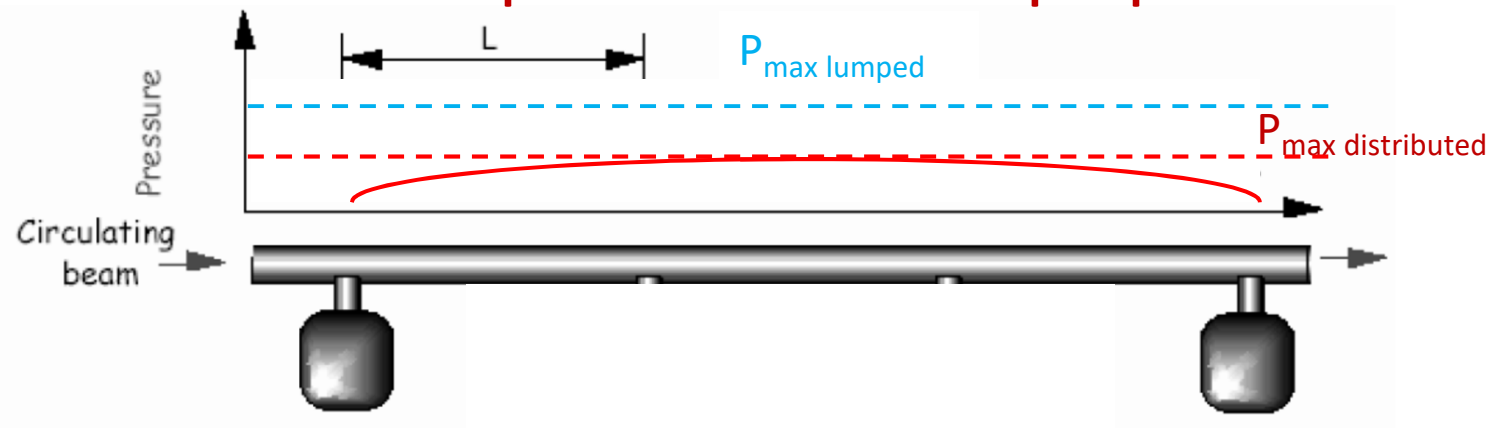


Distributed pumping

Pressure profile with lumped pumps



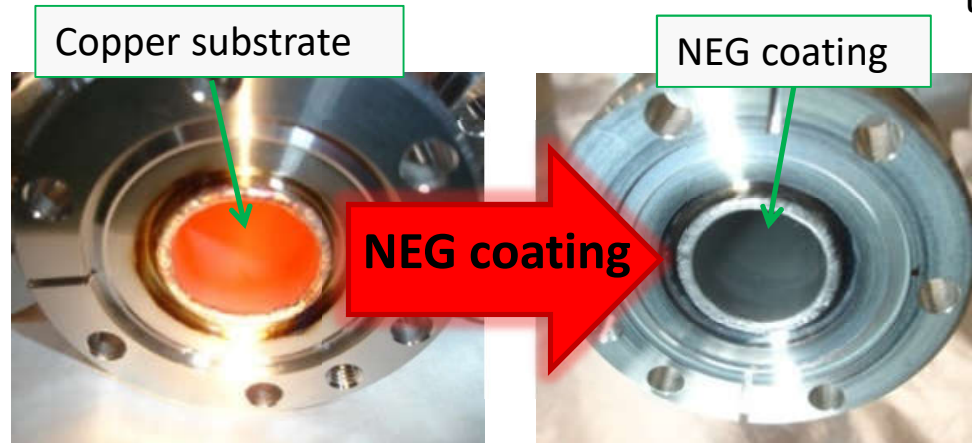
Pressure profile with distributed pumps



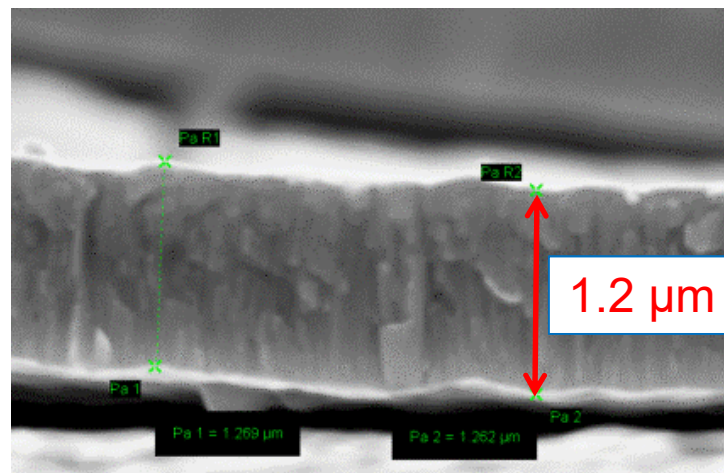
F. Mazzolini, 'The use of NEG pumps and coatings in large vacuum systems: experience and limitations', CAS 2006 Vacuum in accelerators

NEG coatings

NEG (Non-Evaporable Getter) coating transforms a vacuum chamber from a gas source to a vacuum pump.



The technology of coating vacuum chambers by magnetron sputtering was developed at CERN for the warm sections of LHC. Nowadays it is also widely applied in synchrotron radiation sources.



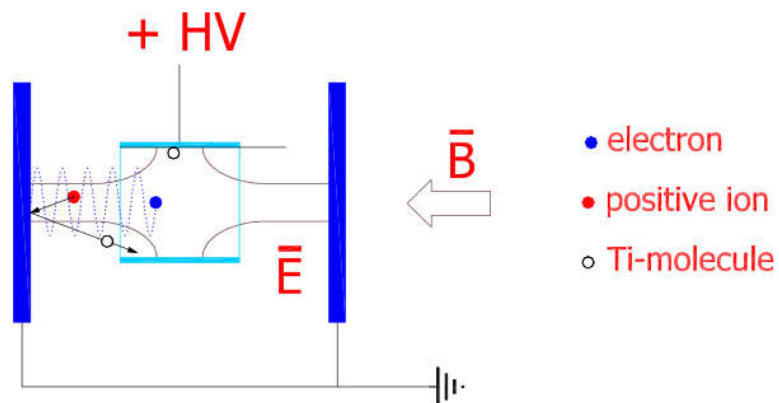
NEG film characteristics:

- Film composition: Ti (30%), Zr (40%), V (30%).
- Thickness $\sim 1 \mu\text{m}$,
- Activation temperature 200°C for 24 h,
- Low PSD (Photon stimulated desorption),
- Sticking probability similar to TSP.

Disadvantage of NEG: has limited capacity and activation cycles.

Sputter ion pumps

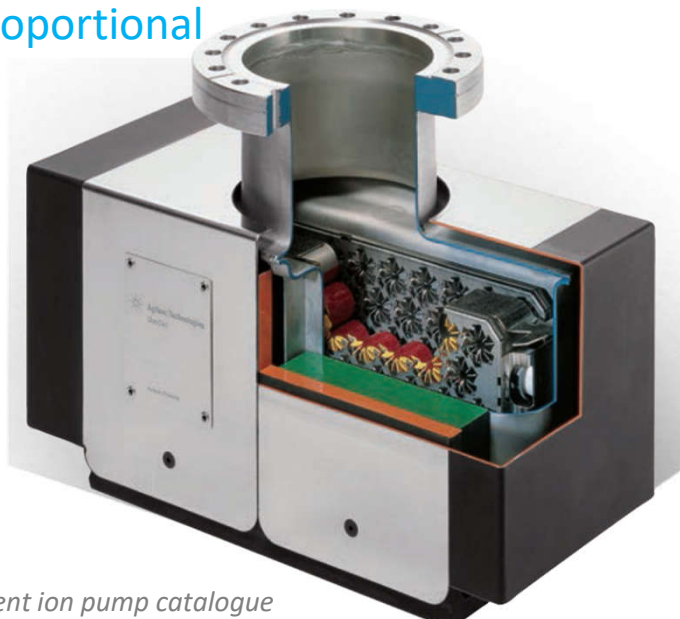
Penning cell



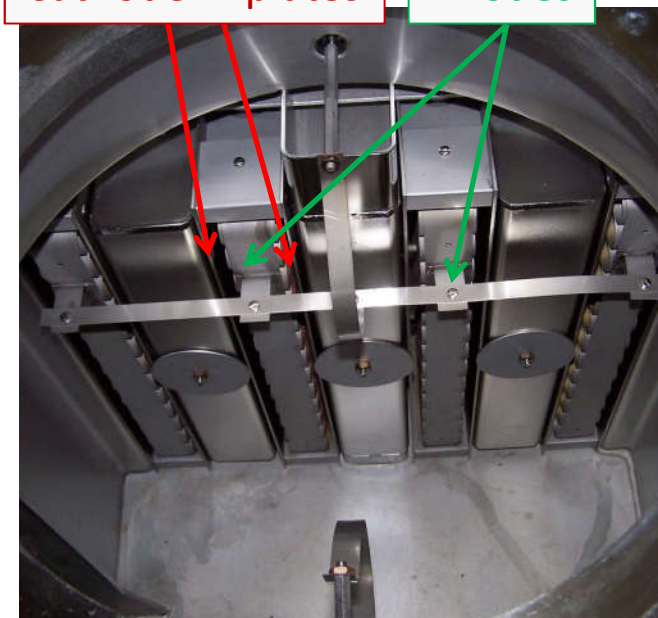
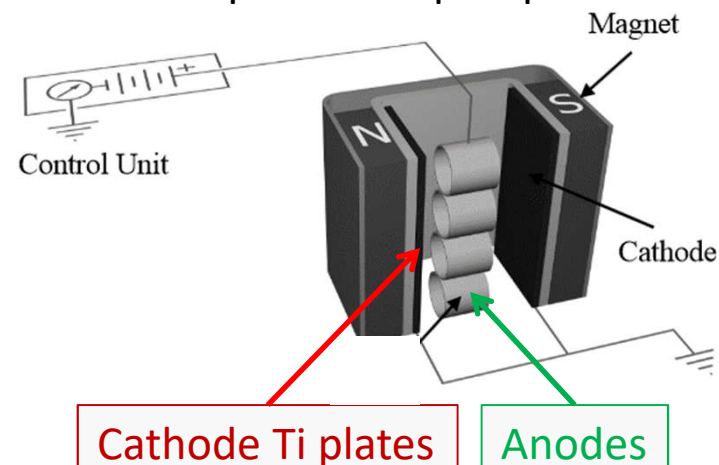
Used for pressure measurement as number of ions is proportional to pressure.

- Voltage 3 to 7 kV,
- Cathodes are plates of Ti at ground potential,
- Magnetic field generated by external permanent magnets ~ 0.1 T.

Agilent ion pump catalogue



Sputter ion pump



Presented on day 3.

L. Schulz, Sputter ion pumps, CAS 1999 proceedings

Sputter ion pumps

Agilent ion pump catalogue

Wide variety of ion pumps to choose:

- **Electrode material and configuration: Diode, noble diode, triode,**
- **Pumping speeds: from 0.2 l/s (weight 0.6 kg) till 500 l/s and more (260 kg)**

S = 500 l/s,
260 kg

S = 0.2 l/s,
0.6 kg



Nominal pumping speed normalized to that of air for diode and triode ion pump:

Gas	Air	N ₂	O ₂	H ₂	CO	CO ₂	H ₂ O	CH ₄	Ar	He
Diode	1	1	1	1.5-2	0.9	0.9	0.8	0.6-1	0.03	0.1
Triode	1	1	1	1.5-2	0.9	0.9	0.8	0.6-1	0.25	0.3

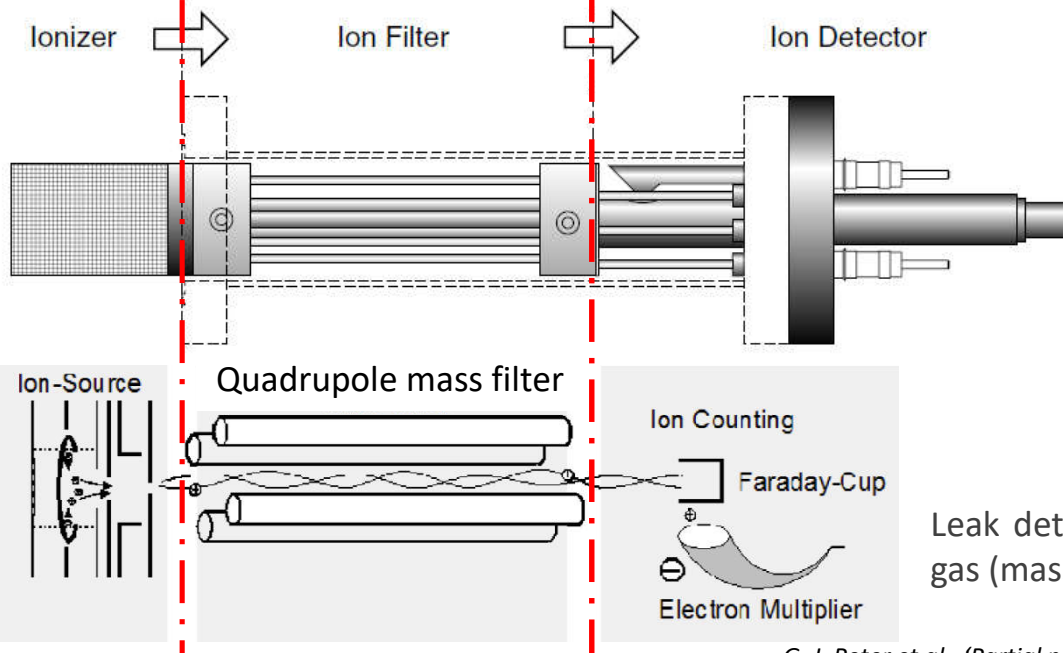
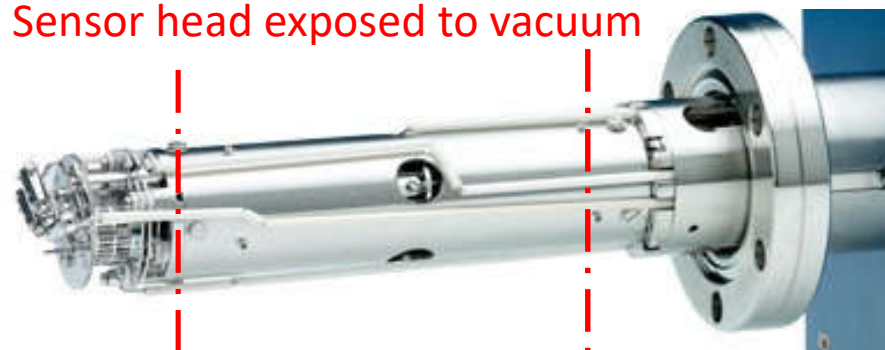
Advantages of ion pumps: clean, bakeable, vibration free (no moving parts), continuous operation, wide operating range 10^{-4} to 10^{-11} mbar, low power consumption, long lifetime at low pressure.

Paolo Chiggiato, Vacuum Technology for Ion Sources, CAS 2012 proceedings

Partial pressure measurement

Residual gas analyzer assembly

Sensor head exposed to vacuum



Residual gas analyzer – (mass spectrometers) used to monitor the quality of vacuum i.e. which gas species are present in the system.

Presented on day 3.

Quadrupole mas filter:

- Ions entering the quadrupole field experience potential differences deflecting them from their original trajectory.
- The extent of deflection of ions is related to its mass to charge (m/e or m/z) ratio.
- At each instance only one m/e ratio resonates with the field allowing the ion to pass along its axis.
- All other species are deflected and neutralised by impact on the quadrupole rods.

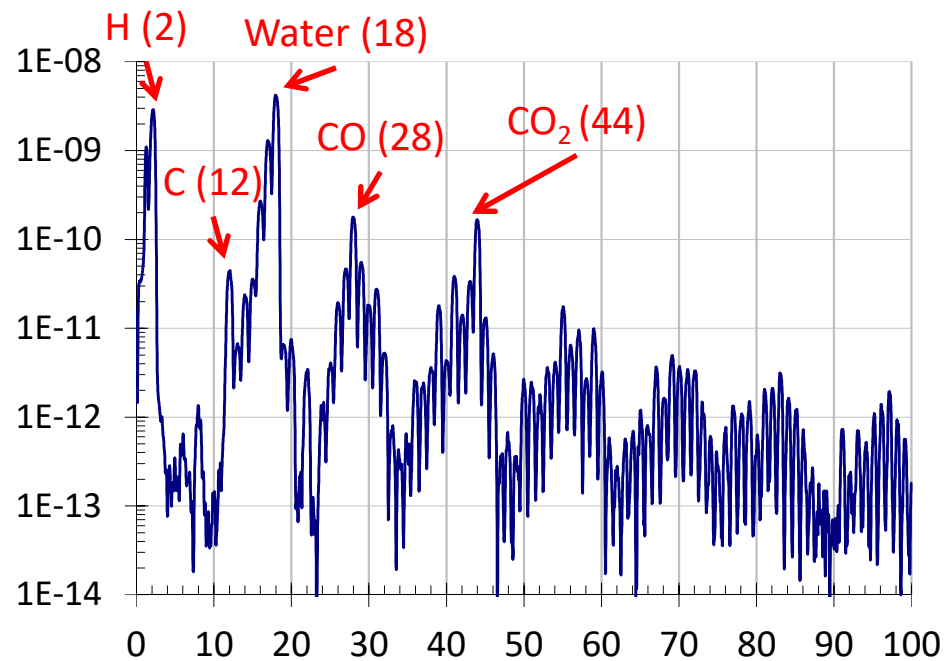
Leak detectors – mass spectrometers set for helium gas (mass 4) usually combined with pumping system.

Presented on day 3.

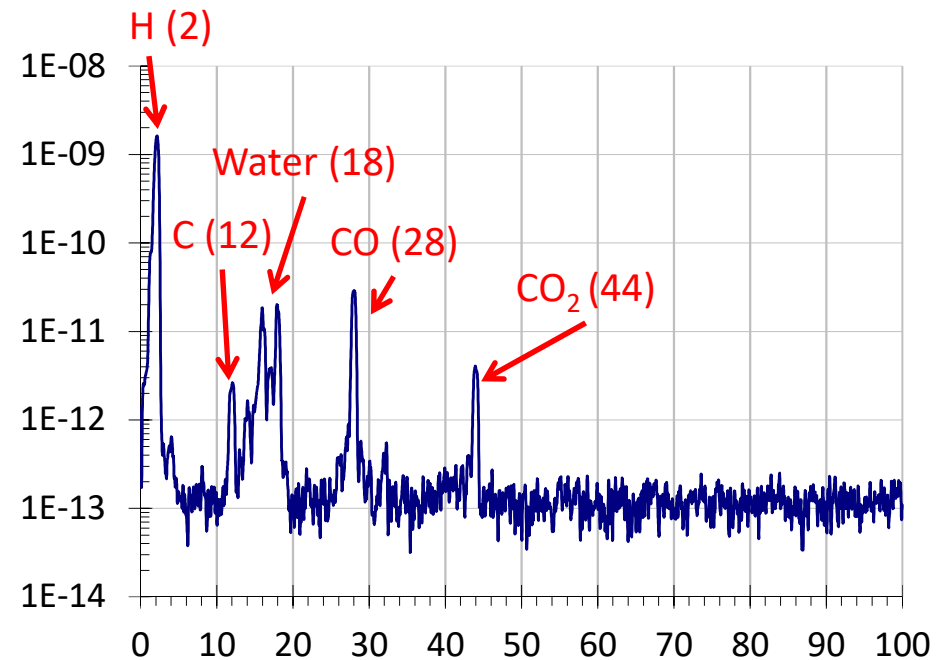
G. J. Peter et al., 'Partial pressure gauges', Vacuum in Accelerators, CAS 2006 proceedings

Residual gas spectrums of an UHV system:

at total pressure 4×10^{-9} mbar



at total pressure 4×10^{-11} mbar

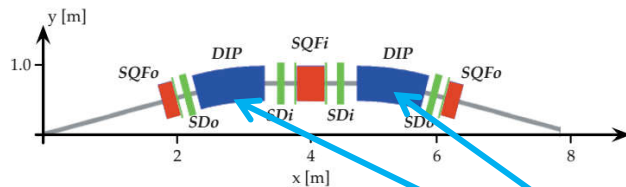


Paolo Chiggiato, Vacuum Technology for particle accelerators, 2013

MAXIV 3 GeV storage ring layout and design

Storage ring layout

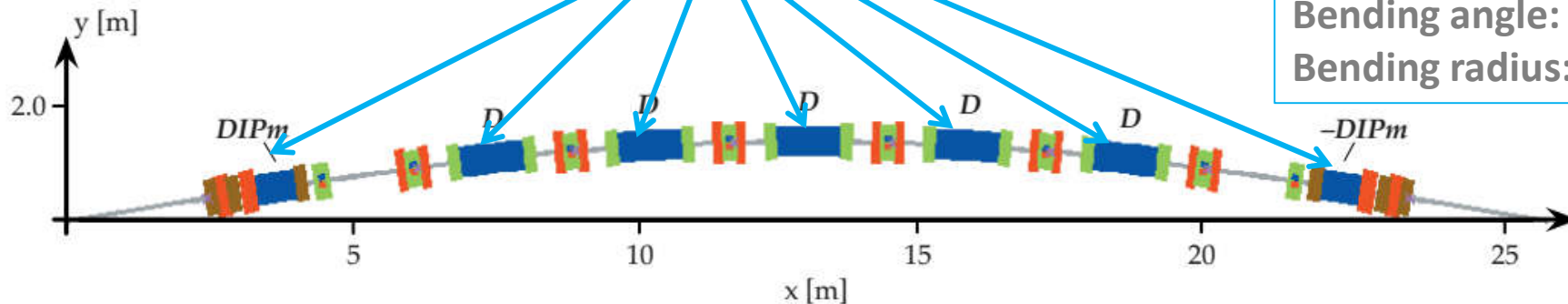
1.5 GeV double-bend achromat (DBA) lattice:



2 dipoles,
Bending angle: 30°
Bending radius: 3.8 m

Energy:	1.5 GeV
Horizontal Emittance (bare lattice):	6 nm rad
Circumference:	96 m
#straight sections:	12 x 3.3 m

3 GeV 7-bend achromat lattice:



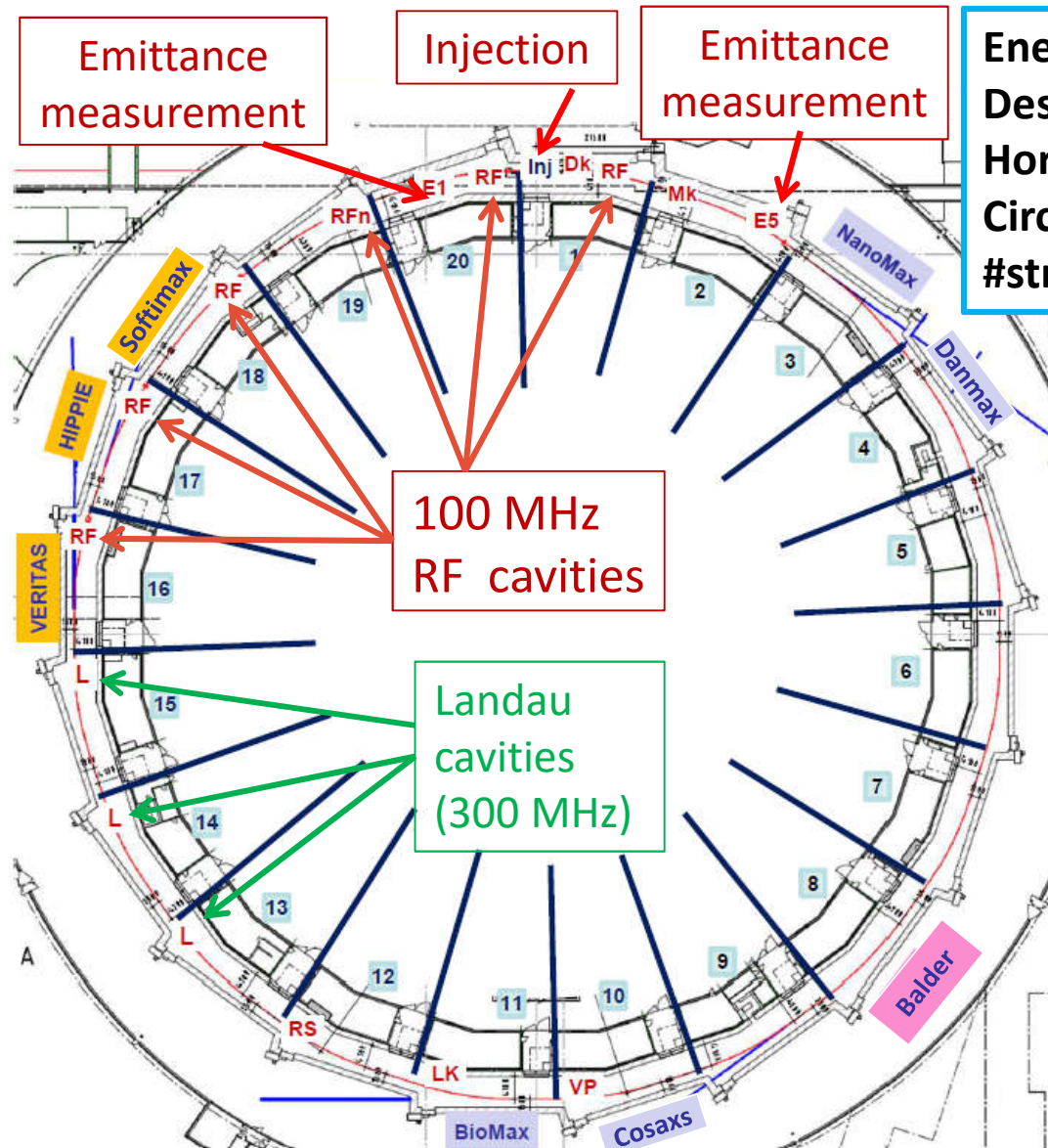
Dipole magnets

7 dipoles,
Bending angle: 18°
Bending radius: 19 m

Lattice of choice for the 3 GeV ring: 7-bend achromat (multi-bend achromat). Choice of such lattice puts major constraints on the vacuum system design.

Energy:	3 GeV
Horizontal Emittance (bare lattice):	0.33 nm rad
Circumference:	528 m
#straight sections:	20 x 4.5 m

3 GeV ring layout



Energy: 3 GeV
Design current: 500 mA
Horizontal Emittance: 0.33 nm rad
Circumference: 528 m
#straight sections: 20 x 4.5 m

Installed Insertion Devices:

4 In-vacuum Undulators:

- NanoMAX, BioMAX, Cosaxs, Danmax,

3 EPU (4 m long, min gap 11 mm):

- VERITAS, HIPPIE, Softimax

1 In-vacuum Wiggler (2.4 m long):

- BALDER IVW50

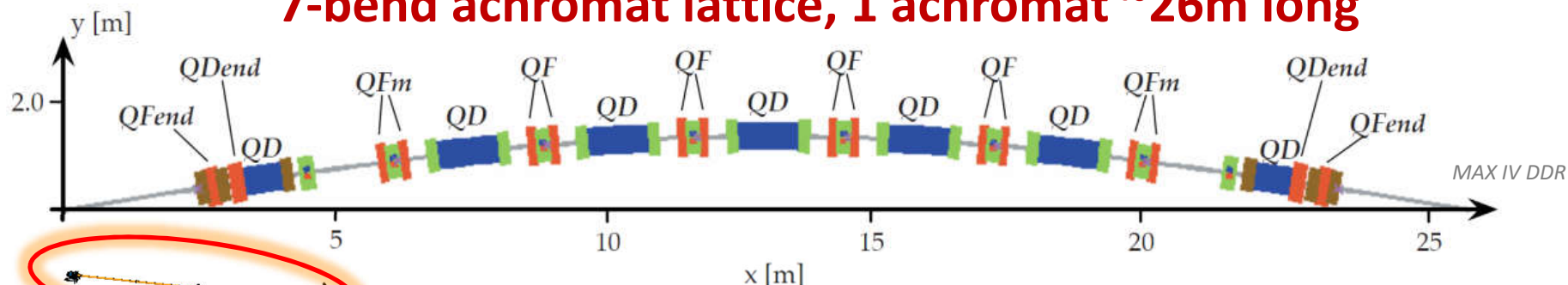
Legend:

- **Dk:** Dipole kicker (S1)
- **Mk:** Multipole kicker (L)
- **Lk:** Longitudinal kicker (S2)
- **VP:** Vertical pinger (S2)

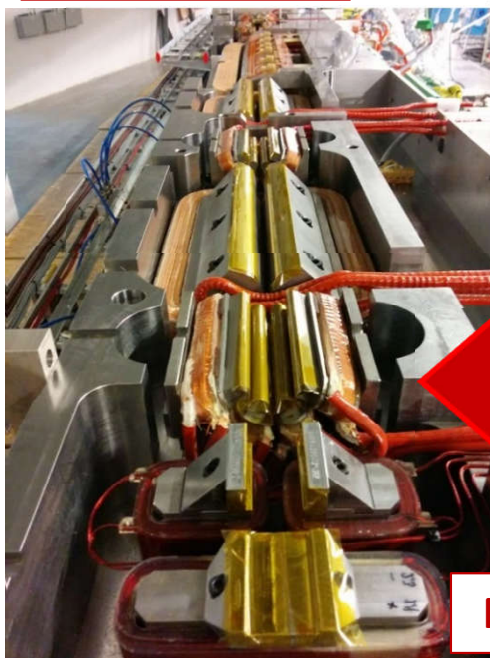
L=long straight,
S=short straight,

3 GeV achromat layout

7-bend achromat lattice, 1 achromat ~26m long



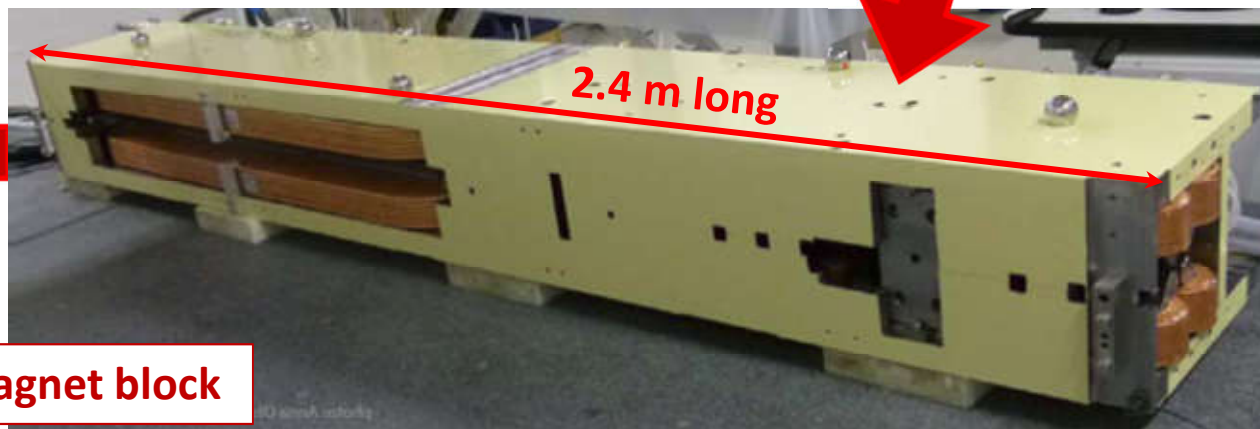
Straight section for
insertion devices



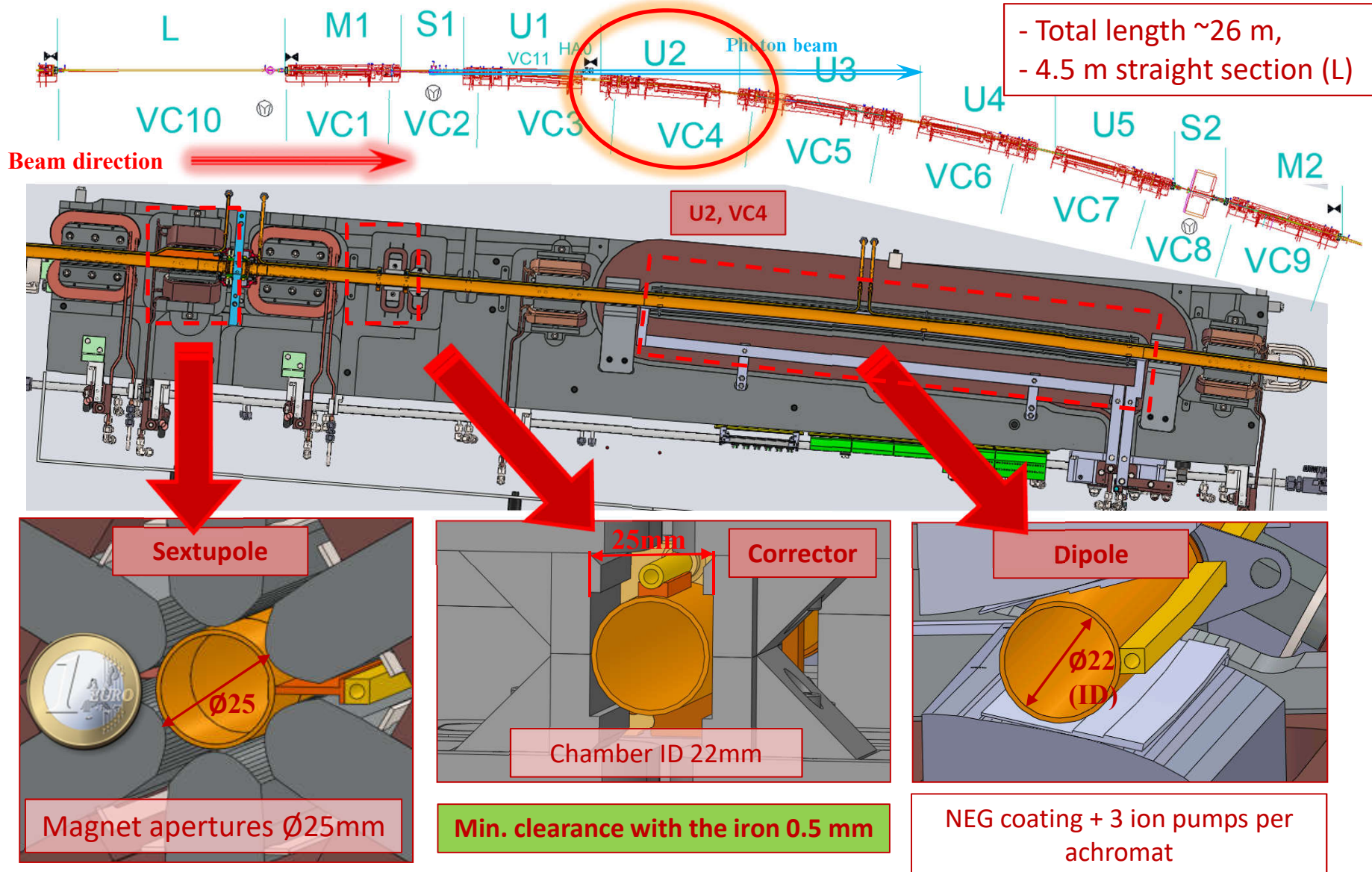
Beam direction

2.4 m long

Magnet block



3 GeV magnet layout



- Compact lattice**

Small longitudinal distance between magnets.

No space for
lumped absorbers

- Closed solid magnet block**

Little place around the magnets.

No space for
lumped pumps

- Small aperture of the magnets**

Magnets' aperture $\varnothing 25$ mm.

Low conductance
of vacuum tubes

- Low target dynamic pressure**

Average pressure $1e-9$ mbar.

Need of pumping
and low PSD

- Removal of the SR power (BM & ID)**

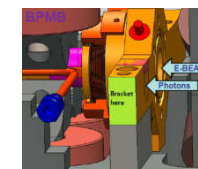
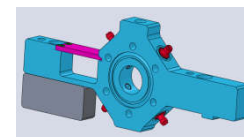
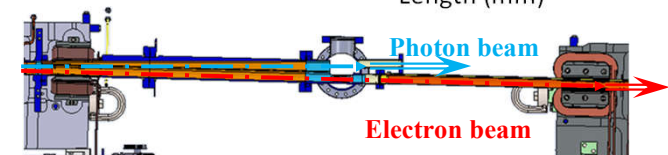
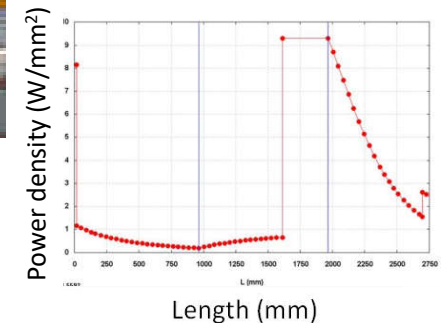
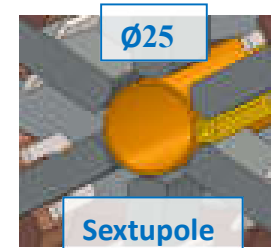
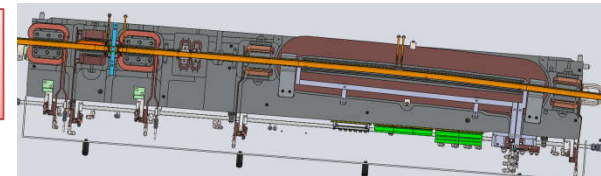
Power density along bent vacuum chamber walls and absorbers.

- Extraction of synchrotron radiation**

Limited by small bending angle.

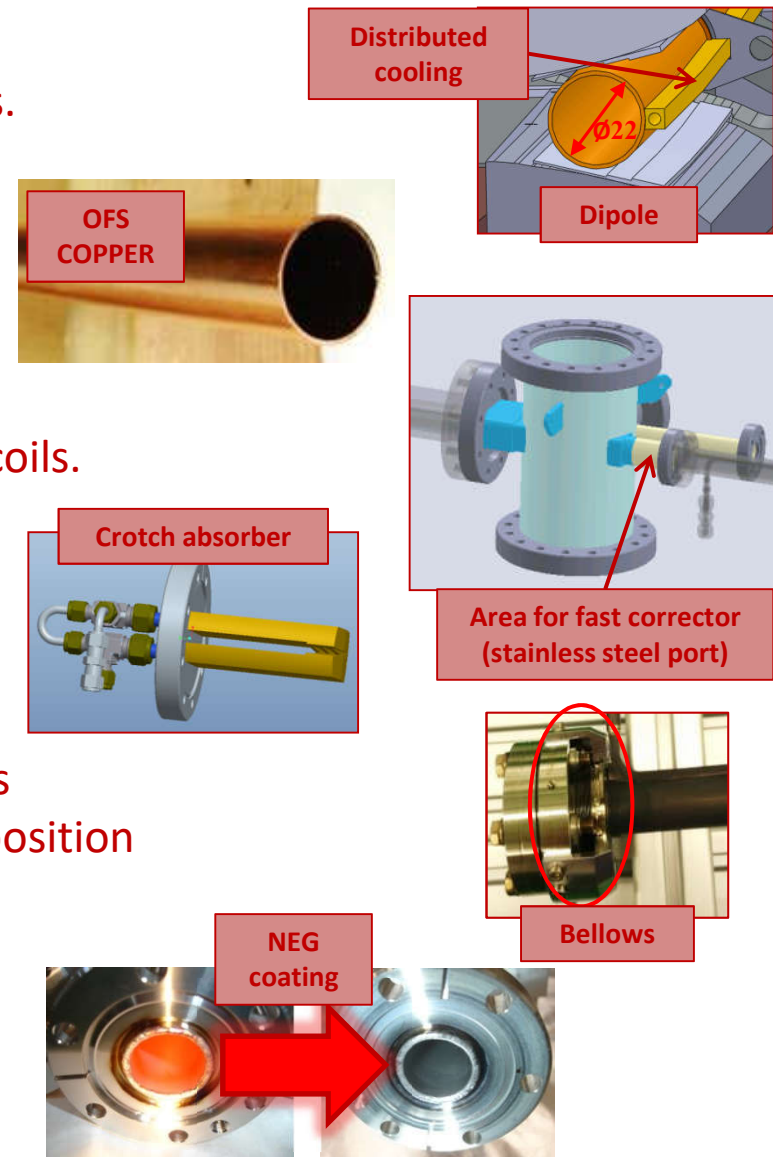
- Stable positioning of BPM**

Disentangling the BPMs from the chambers.

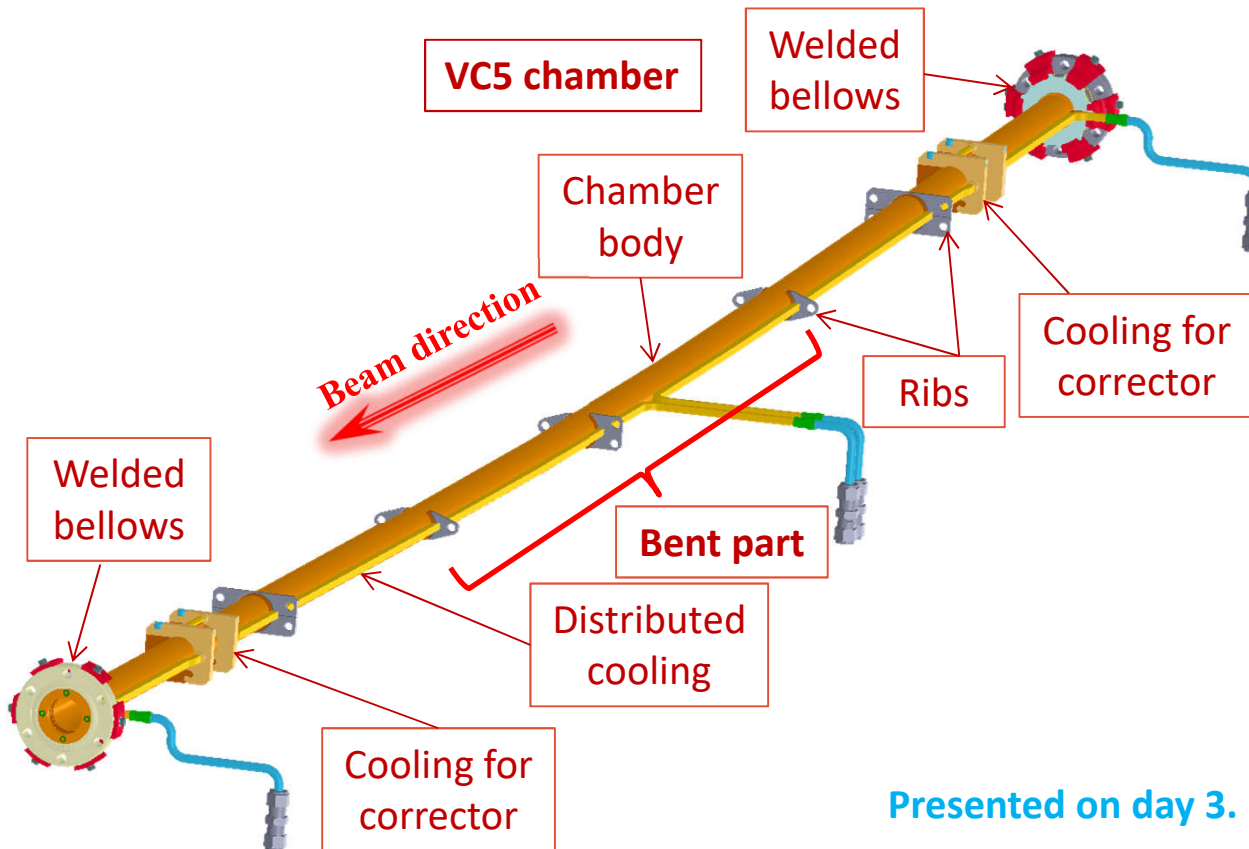
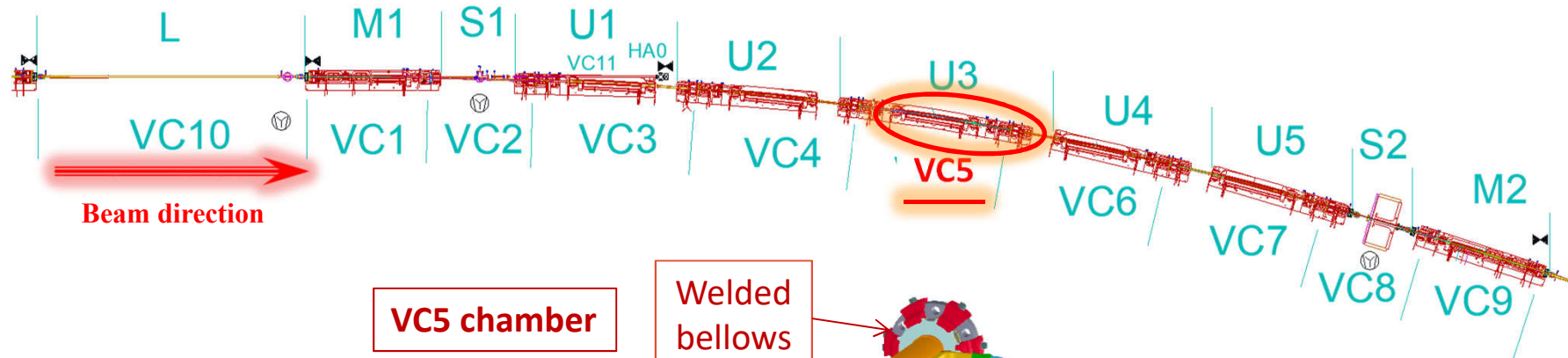


Vacuum system approach

- **Geometry:** inside diameter **22 mm**, **1 mm** wall thickness, bends of 1.5° and 3° over 19 m radius.
 - **Substrate:** **Silver bearing (OFS) Copper** vacuum chambers (resistance to thermal cycling).
 - **Distributed water cooling** to cope with SR.
 - Areas made of **stainless steel** for fast corrector coils.
 - One **Lumped absorber** per achromat needed to extract the photon beam to the front ends.
 - **Welded bellows** at vacuum chamber extremities to allow expansion without affecting the BPM position and temperature.
- Distributed pumping and low PSD all along the conductance limited chamber, utilizing thin film **NEG-coating**.



Standard vacuum chamber geometry



Material: OFS copper

**Inside diameter: 22 mm,
Total length: 2.5 m,**

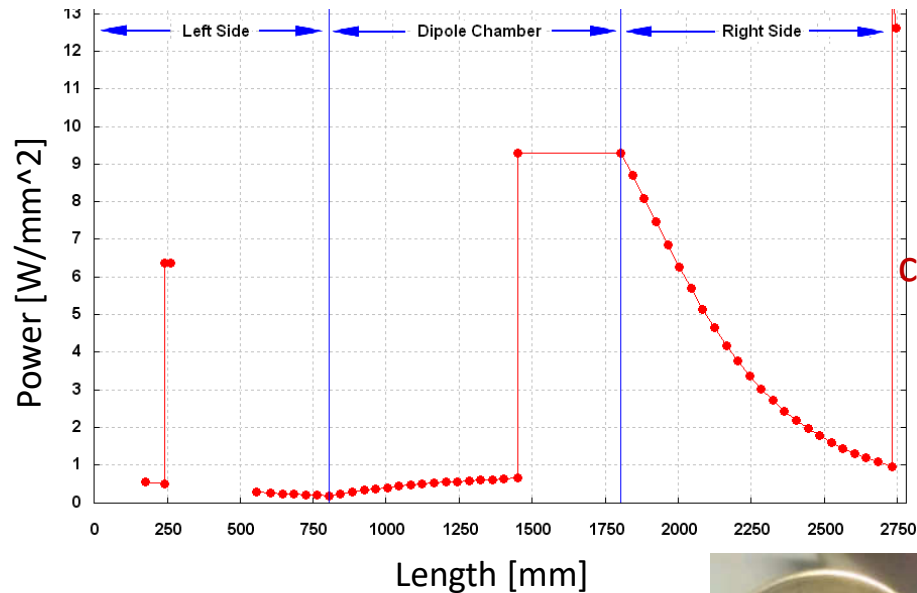
**Bent part
Arc length: 1 m,
Bending angle: 3°,
Bending radius: 19 m.**

NEG-coated.

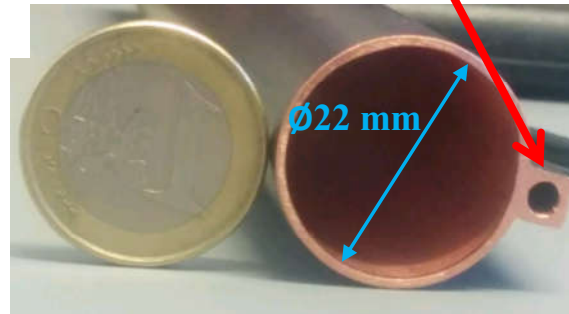
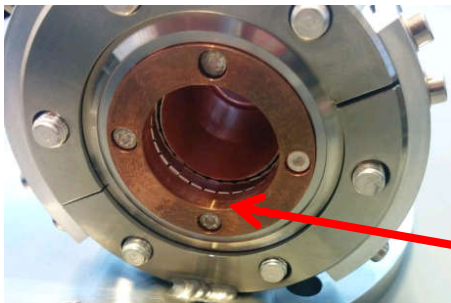
Presented on day 3.

3 GeV standard vacuum chamber geometry

Power density deposited by synchrotron radiation on the outer wall of vacuum chamber vs. length



NEG coated inside



Welded bellows with RF shielding

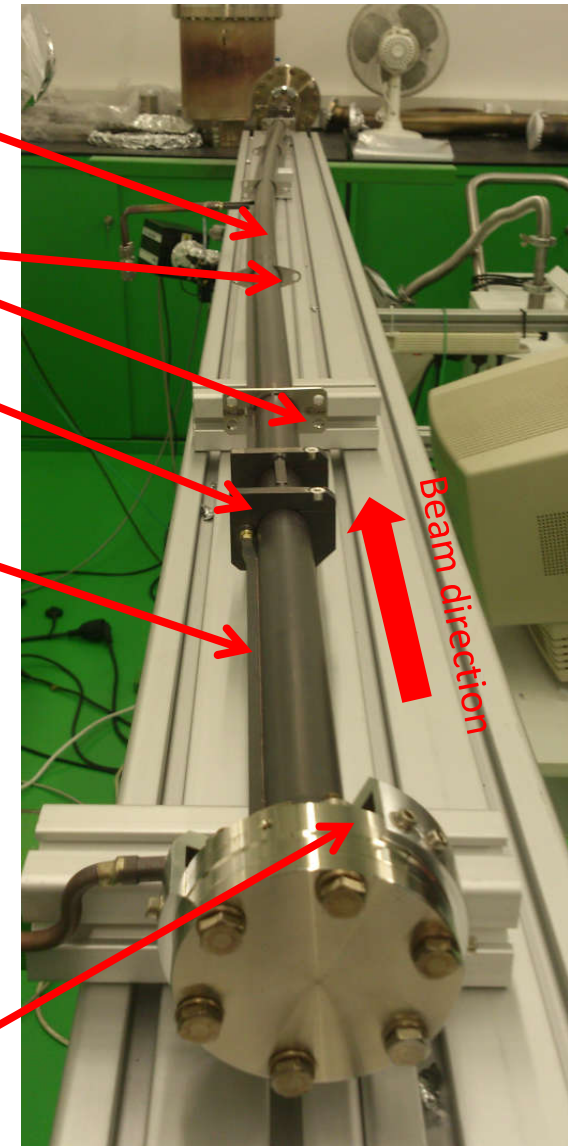
Copper Chamber body

Ribs

Cooling for corrector area

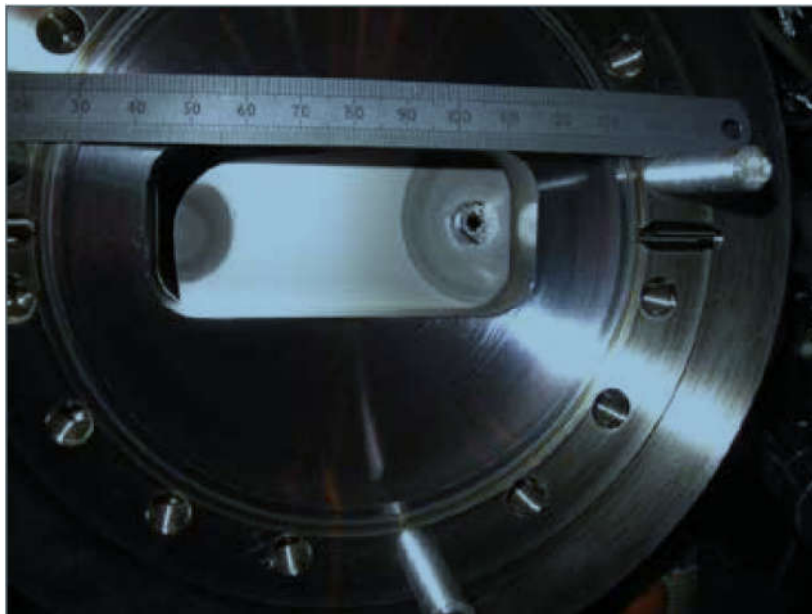
Distributed cooling

Beam direction



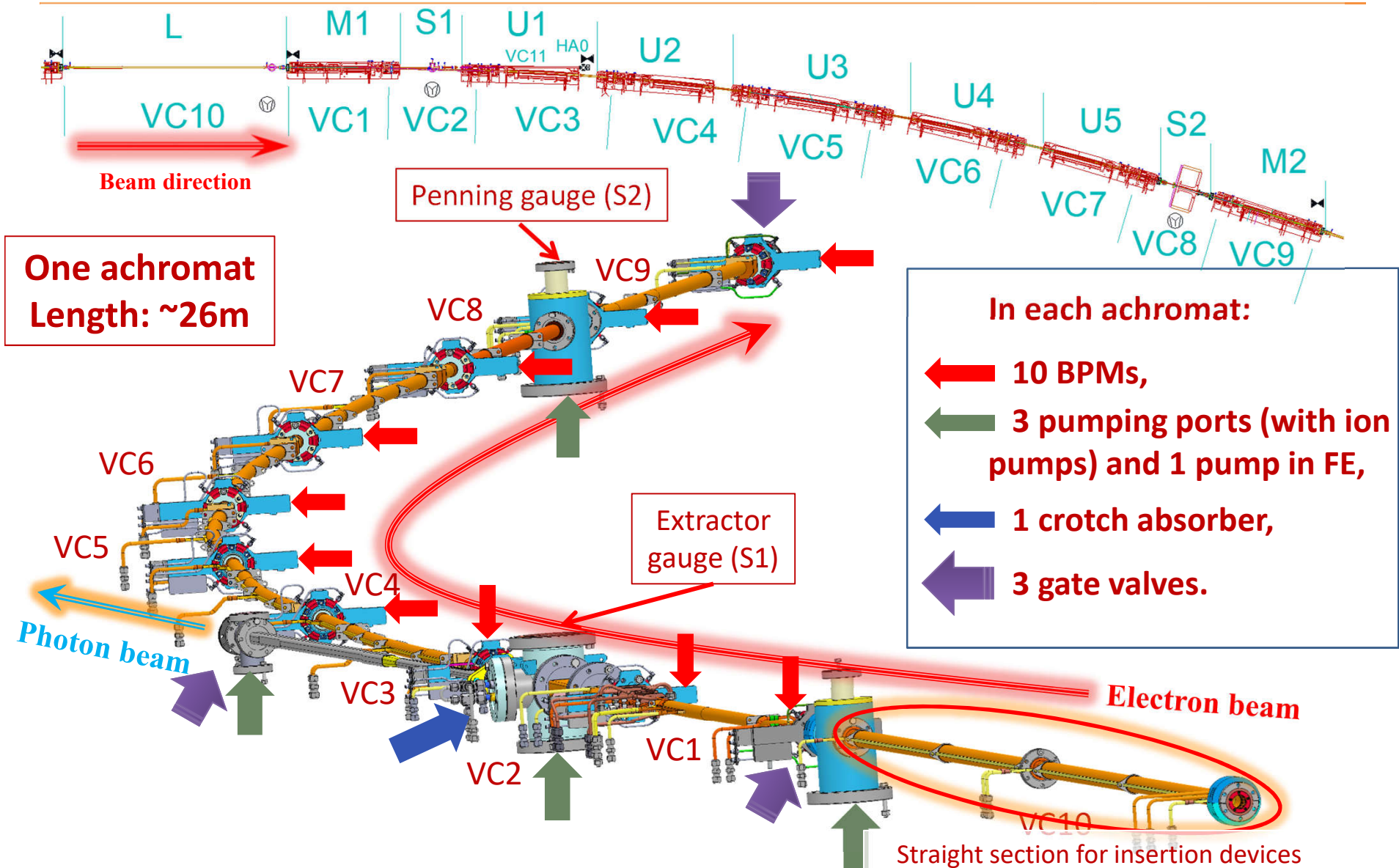
Consequences of excess power

Melted hole in fast closing vacuum valve titanium plate due to undulator beam

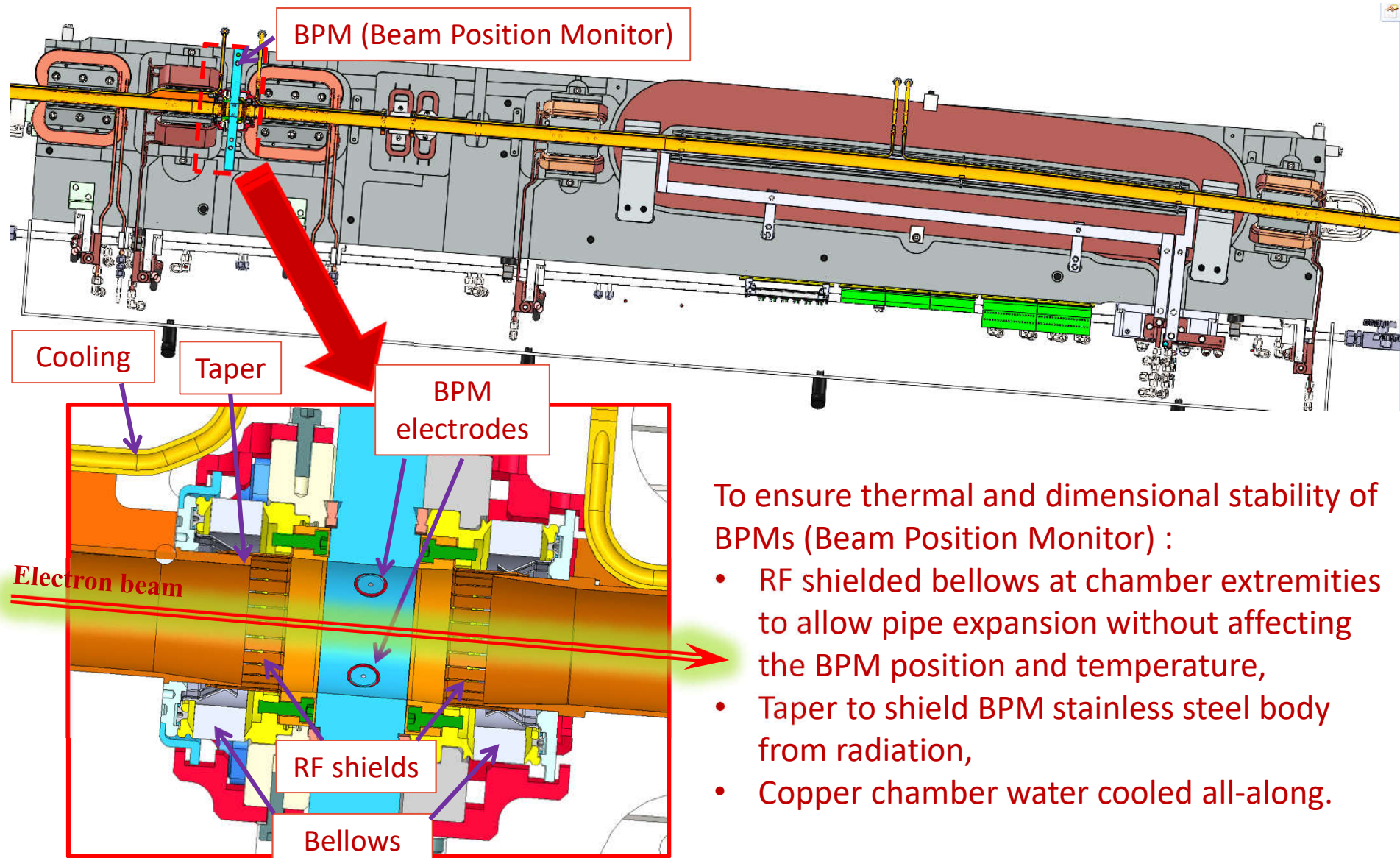


Diamond Light Source Vacuum Systems: The First Seven Years of User Operations, OLAV IV 2014, Matthew Cox

Vacuum achromat layout



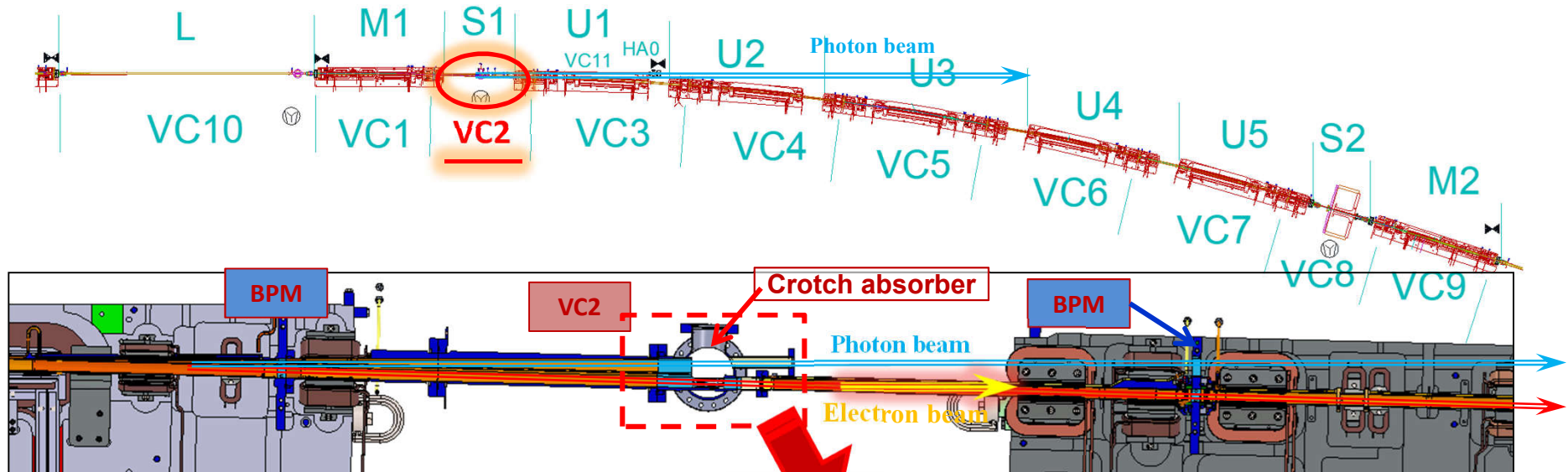
BPM stability



To ensure thermal and dimensional stability of BPMs (Beam Position Monitor) :

- RF shielded bellows at chamber extremities to allow pipe expansion without affecting the BPM position and temperature,
- Taper to shield BPM stainless steel body from radiation,
- Copper chamber water cooled all-along.

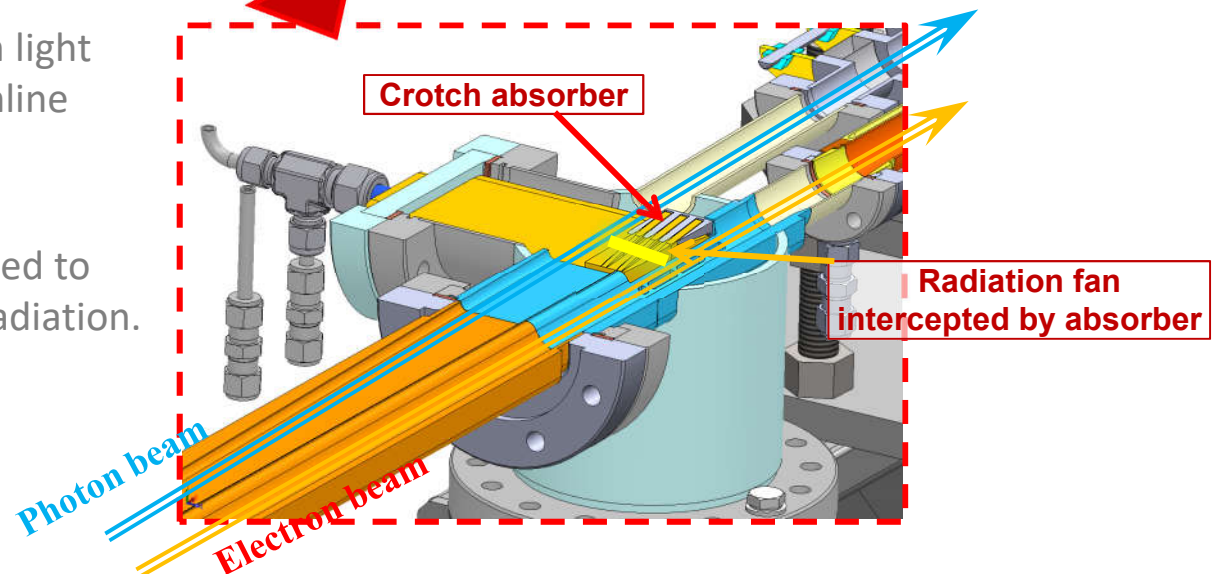
Synchrotron light extraction



Short straight section 1 – synchrotron light extraction to the Front End and Beamline

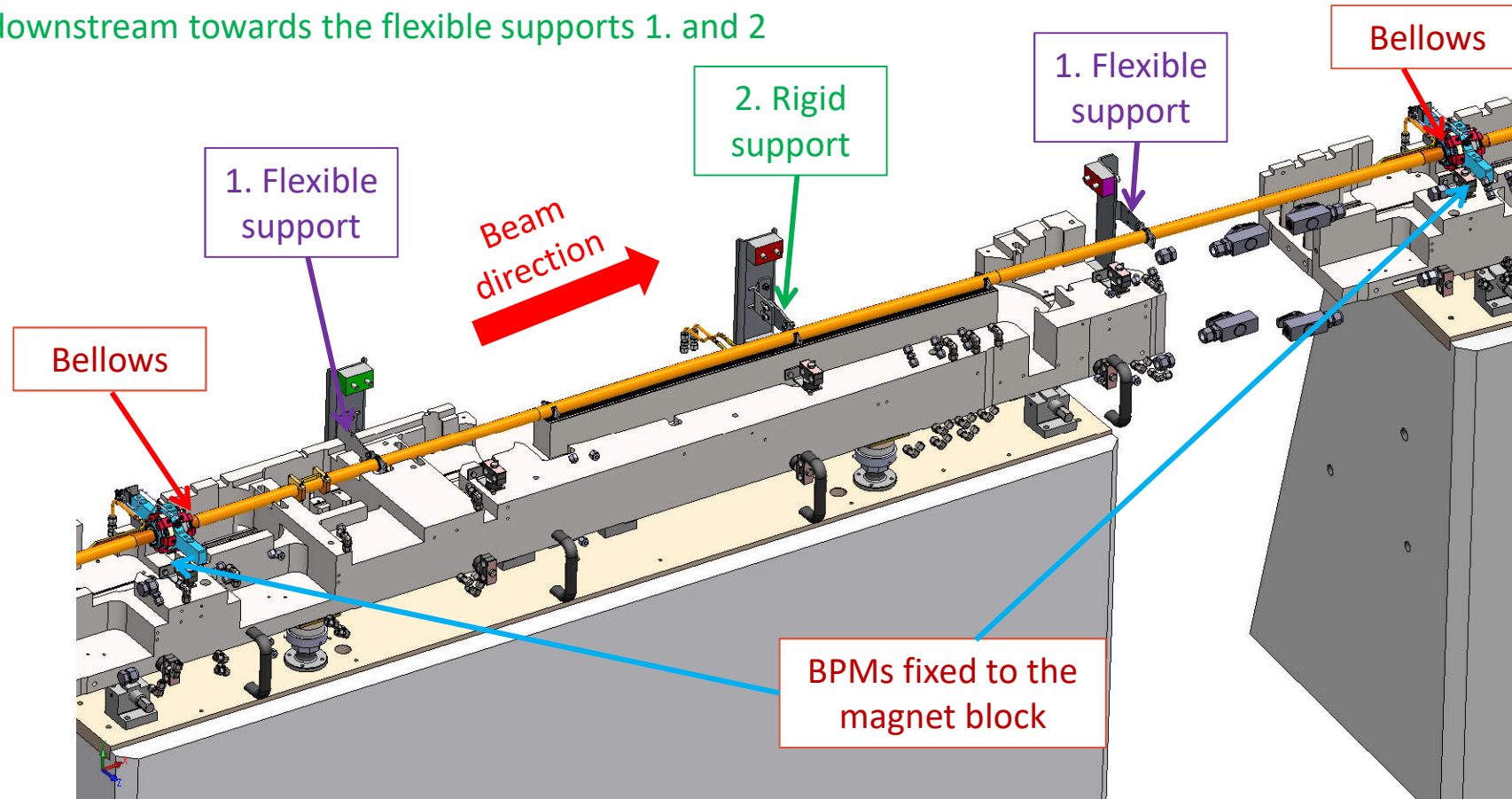
Under the absorber ion pump mounted to remove excess of gas and intercept radiation.

Presented on day 3.



Chamber fixation

1. Flexible support: allows longitudinal movement of the chamber in order to release the stresses from the chamber and block the transversal movement.
2. Rigid support: fixes the chamber in the middle of the dipole part and keeps the chamber in its nominal position both in transversal plane and longitudinally, allowing the chamber to expand upstream and downstream towards the flexible supports 1. and 2

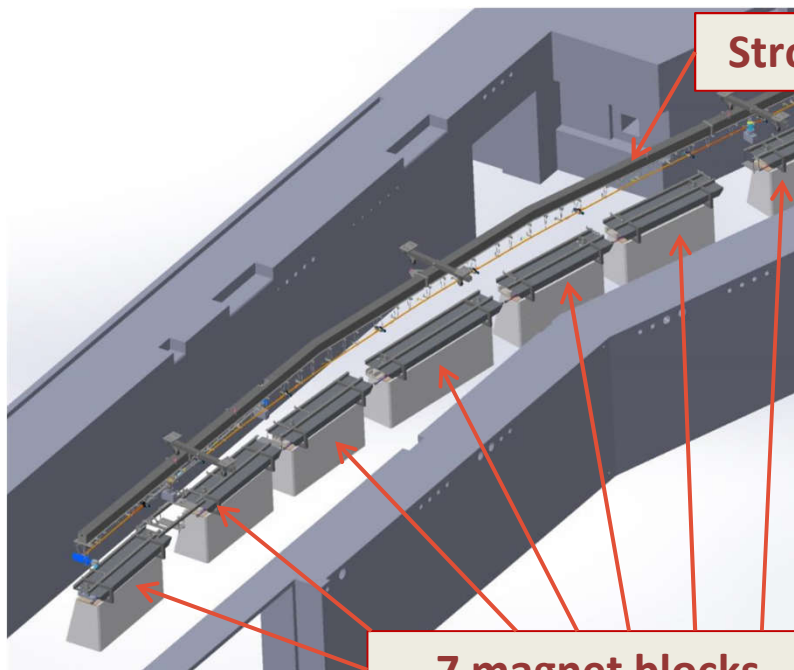


MAXIV 3 GeV storage ring installation

Installation procedure

Installation of NEG-coated ring

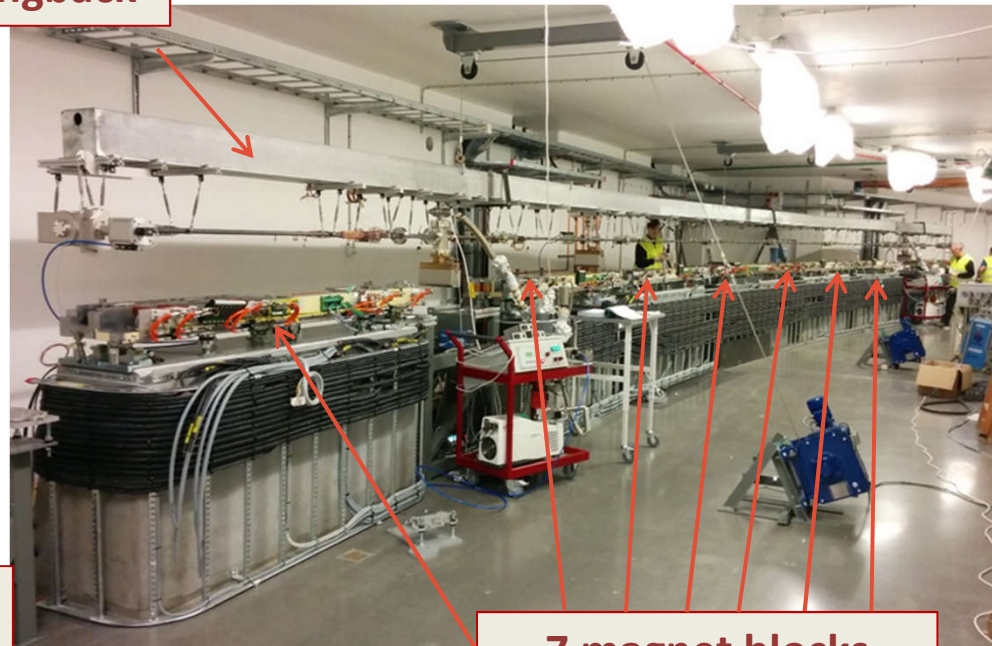
Tunnel view



Strongback

7 magnet blocks
on concrete girders

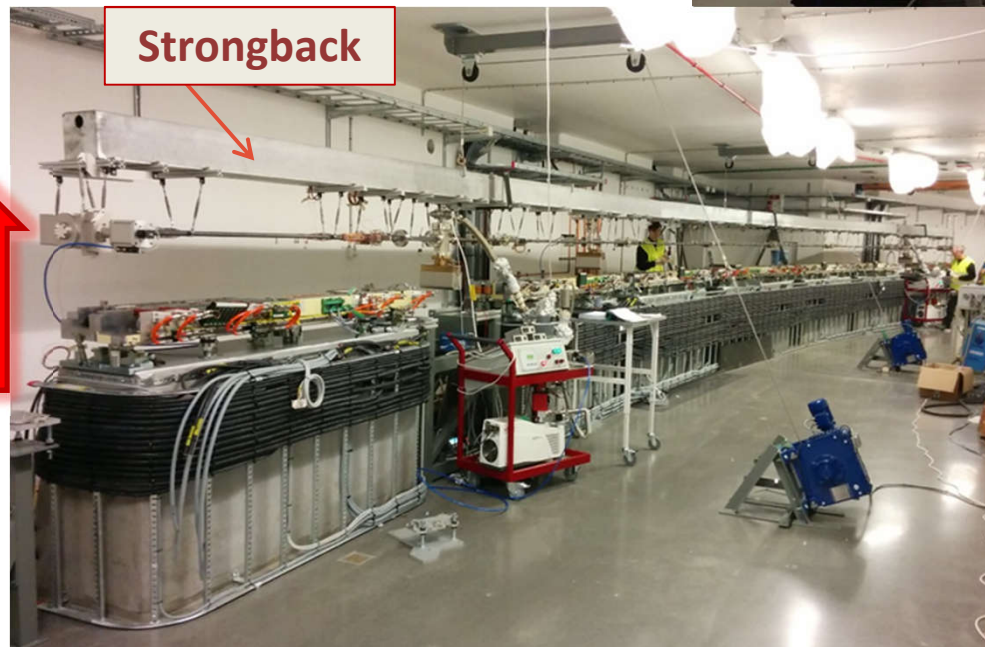
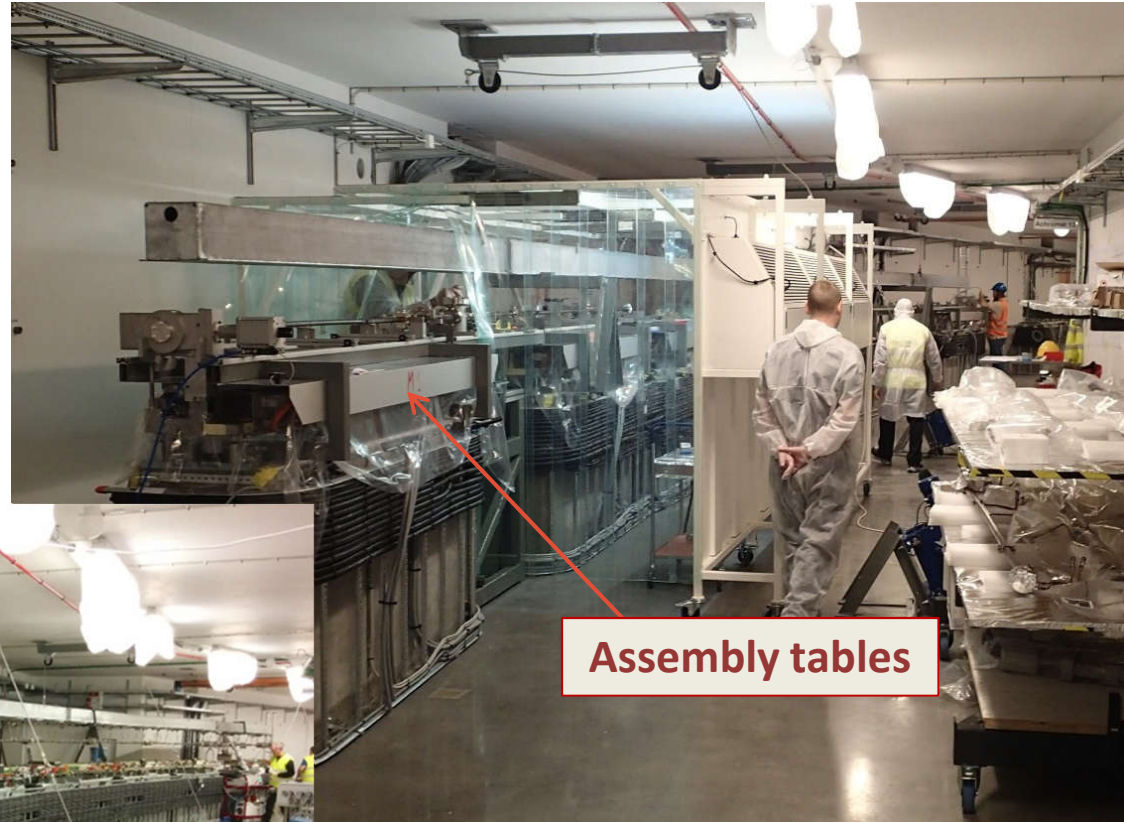
Actual installation started in
November 2014, ended June 2015



7 magnet blocks
on concrete girders

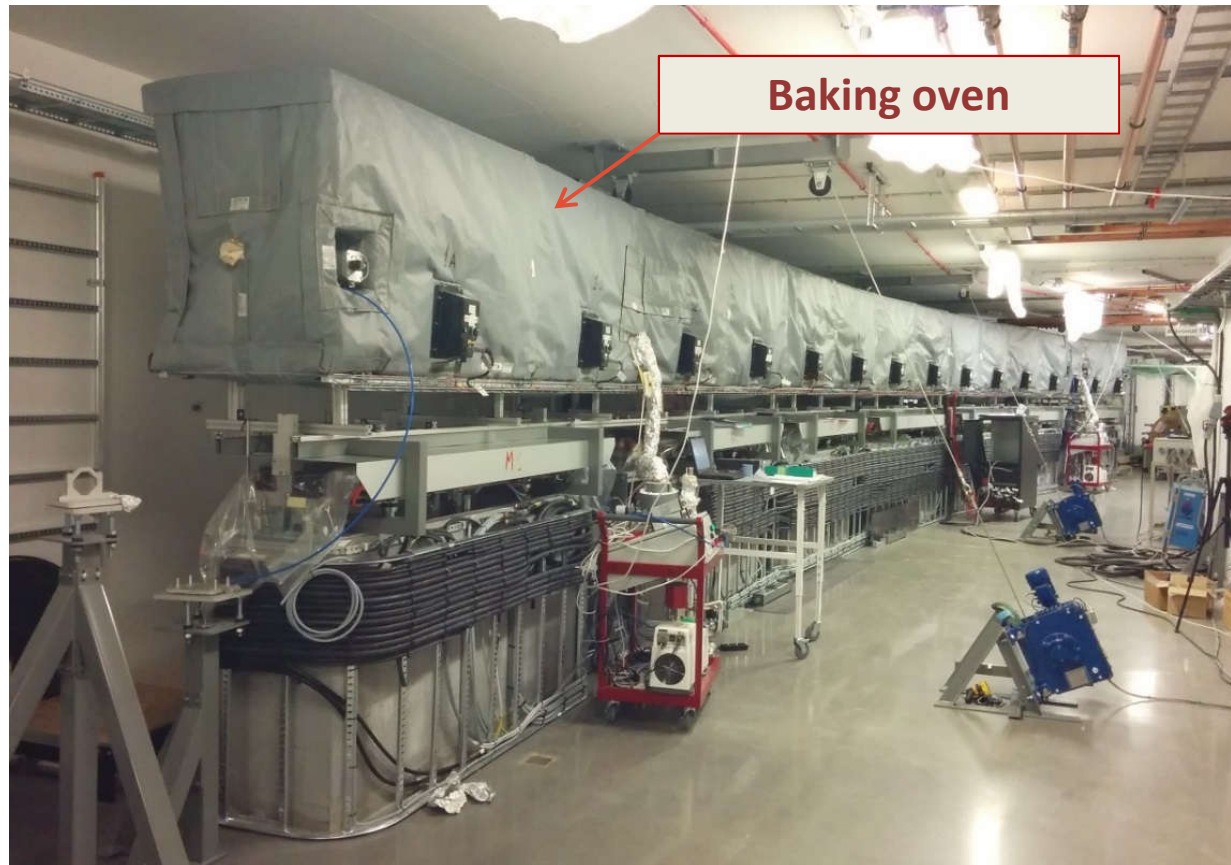
Installation procedure

- Assembly insitu (above magnets),
- **Pumpdown with turbomolecular pumping stations and leak testing with leak detectors,**
- Lifting,



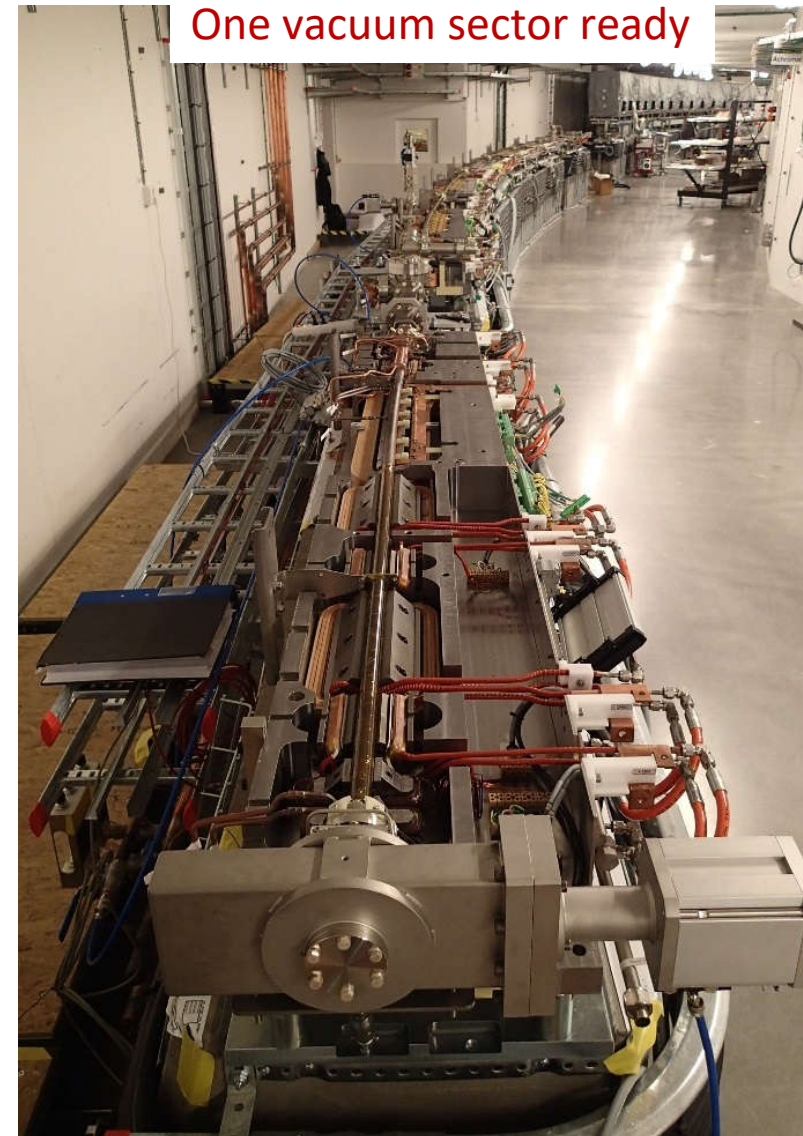
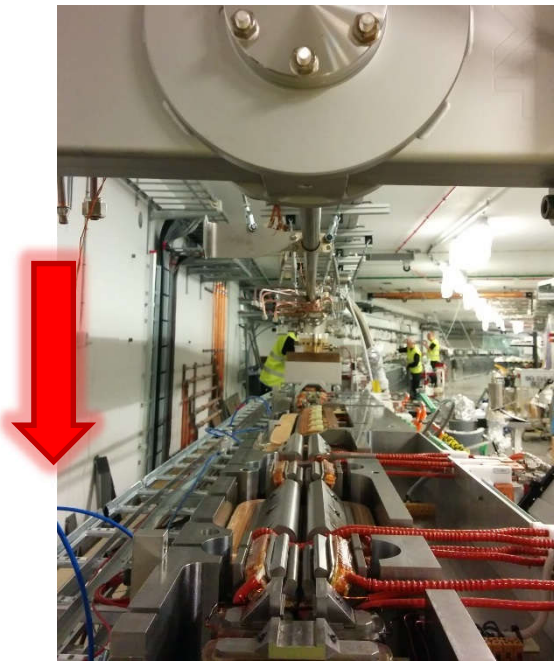
Installation procedure

- **Baking** under vacuum at 160 deg C (1 day),
- NEG activation at 190 deg C (1 day),



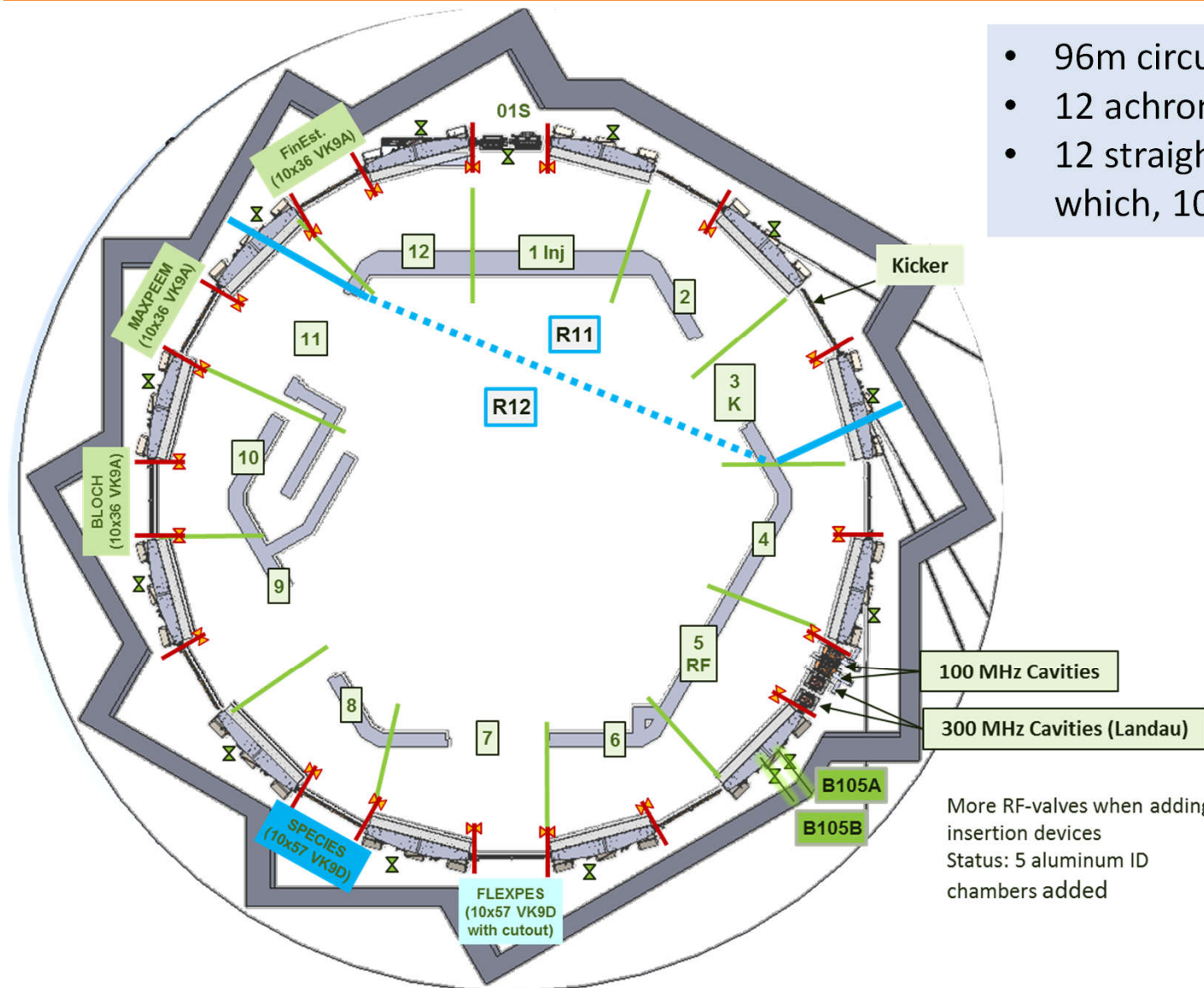
Installation procedure

- Lowering to the bottom magnet half,
- Installation of final equipment (supports, BPM cables),
- closing magnet blocks.



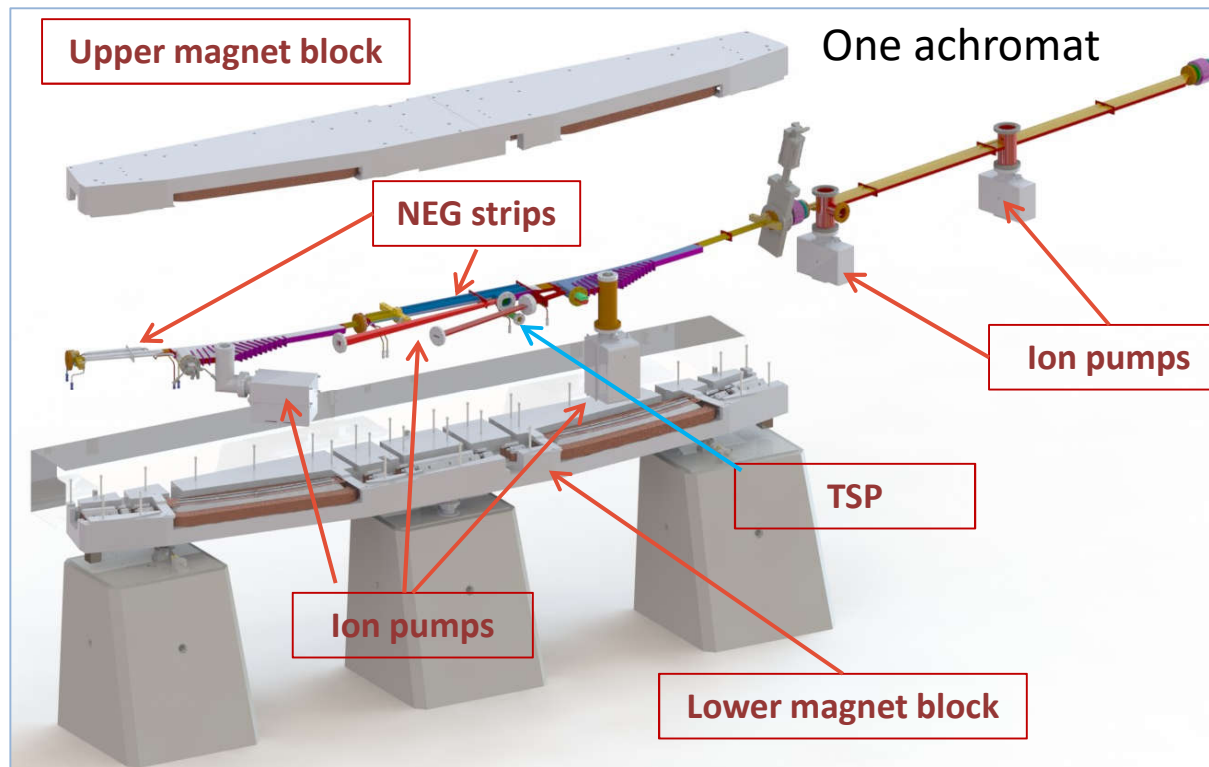
MAXIV 1.5 GeV storage ring layout and design

1.5 GeV storage ring layout



- 96m circumference
- 12 achromats (cells).
- 12 straight sections of which, 10 for IDs.

1.5 GeV storage ring vacuum system



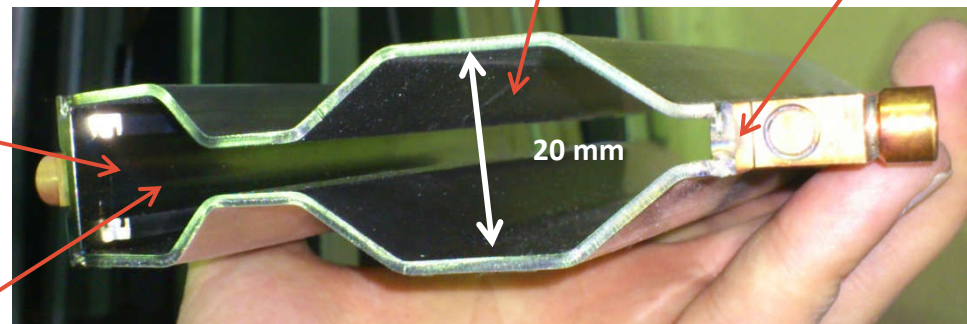
Conventional vacuum system:

- St. steel VC with lumped and distributed absorbers to intercept synchrotron radiation.
- 5 Ion pumps, 1 TSP and 2 NEG strips.



Place for NEG strip

Antechamber for pumping





***Thank you for
your attention***

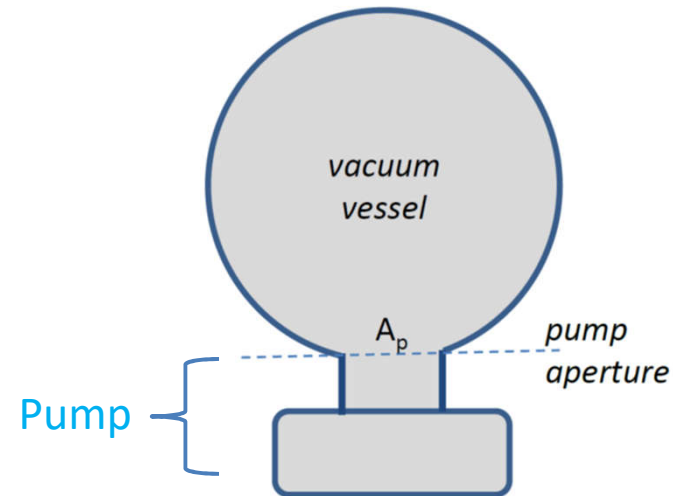
Backup slides

Gas flow in molecular regime

In vacuum technology a pump is an object that permanently removes gas molecules from the gas phase.

Pumping speed S of a pump is defined as the ratio between the pump throughput Q_p and the pressure P at the entrance to the pump.

$$S = \frac{Q_p}{P} \quad \left[\frac{l}{s} \right]$$



From the definition of pumping speed:

$$S = A_p C' \alpha$$

A_p – is the area of the pump aperture [cm^2]

C' – is the conductance of the unit surface area for given gas [$\frac{l}{s \text{ cm}^2}$]

α – is the capture probability

Gas flow in molecular regime

Introduced limitation between pump and pumped vacuum volume limits the nominal pumping speed of chosen pump.

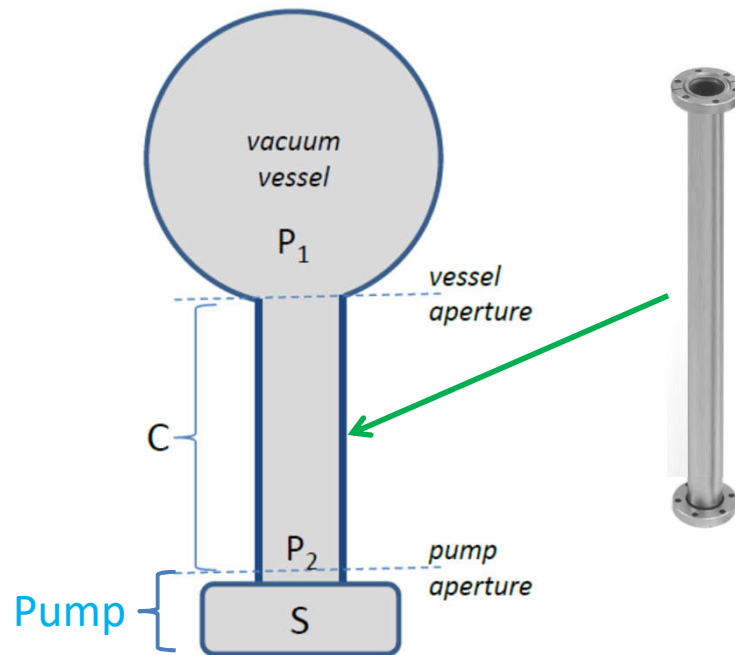
Example:

Conductance of 1 m long tube of 3,8 cm inside diameter (standard DN40CF vacuum pipe) for air (mass 28) is: 6,6 [l/s]

Connected pump of 100 [l/s] to the tube will result in the effective pumping speed S_{eff} :

$$\frac{1}{S_{eff}} = \frac{1}{100 \text{ l/s}} + \frac{1}{6,6 \text{ l/s}} = 0,16$$

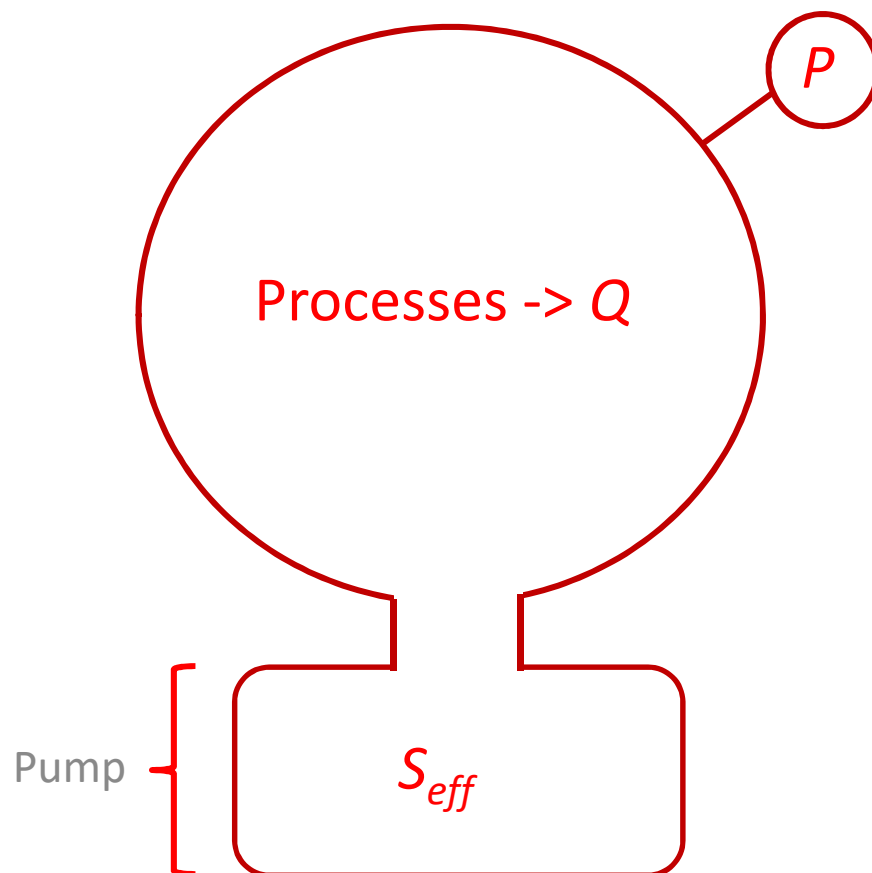
$$\Rightarrow S_{eff} = 6,3 \text{ l/s}$$



$$\frac{1}{S_{eff}} = \frac{1}{S} + \frac{1}{C}$$

$$\Rightarrow S_{eff} = 6,3 \text{ l/s}$$

Generic vacuum system



$$P = \frac{Q}{S_{eff}}$$

P – gas pressure,
 Q – gas load (outgassing),
 S_{eff} – Effective pumping speed.

Capture pumps: getters

Getter materials adsorb gas molecules on their surface which is contamination and native oxide layer free. Such surface can be produced in two ways:

- sublimating (evaporating) the reactive metal *in situ*: **evaporable getters** or **sublimation pumps**,
- dissolving the surface contamination into the bulk of the getter material by heating: **non-evaporable getters (NEG)**; the dissolution process is called **activation**.

Getter surface is characterized by the **sticking probability 'α'**:

$$\alpha = \frac{\text{number of molecules captured}}{\text{number of molecules impinging}}$$

Getter pumping speed (S):

$$S = \alpha A_{\text{getter}} C'$$

Where:

A_{getter} surface area of active getter surface,
 C' conductance for given gas of unit surface area.

Getter materials do not pump **noble gases** and **methane (CH₄)** at room temperature. Therefore, they need auxiliary pumping to keep a stable pressure.

Evaporable Getters

Evaporable getters: TSP – Titanium Sublimation Pump

Titanium (Ti) is the **sublimated** metal. Ti filaments are heated up to 1500°C reaching Ti vapour pressure which is deposited on the surrounding surfaces creating a chemically active surface where gas molecules are captured.

When the deposited film is saturated, new sublimation is needed to recover the initial pumping speed. A single filament withstands hundreds of sublimation cycles

Sticking probabilities:

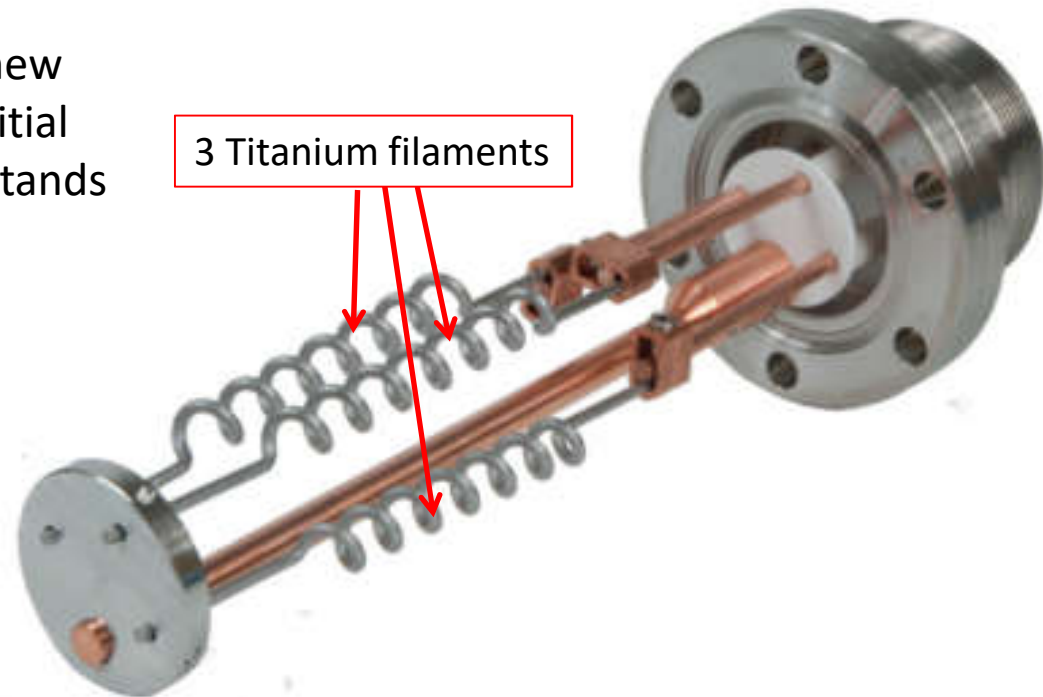
$$H_2: 0.01 \leq \alpha \leq 0.1$$

$$CO: 0.5 \leq \alpha \leq 1$$

Film capacity:

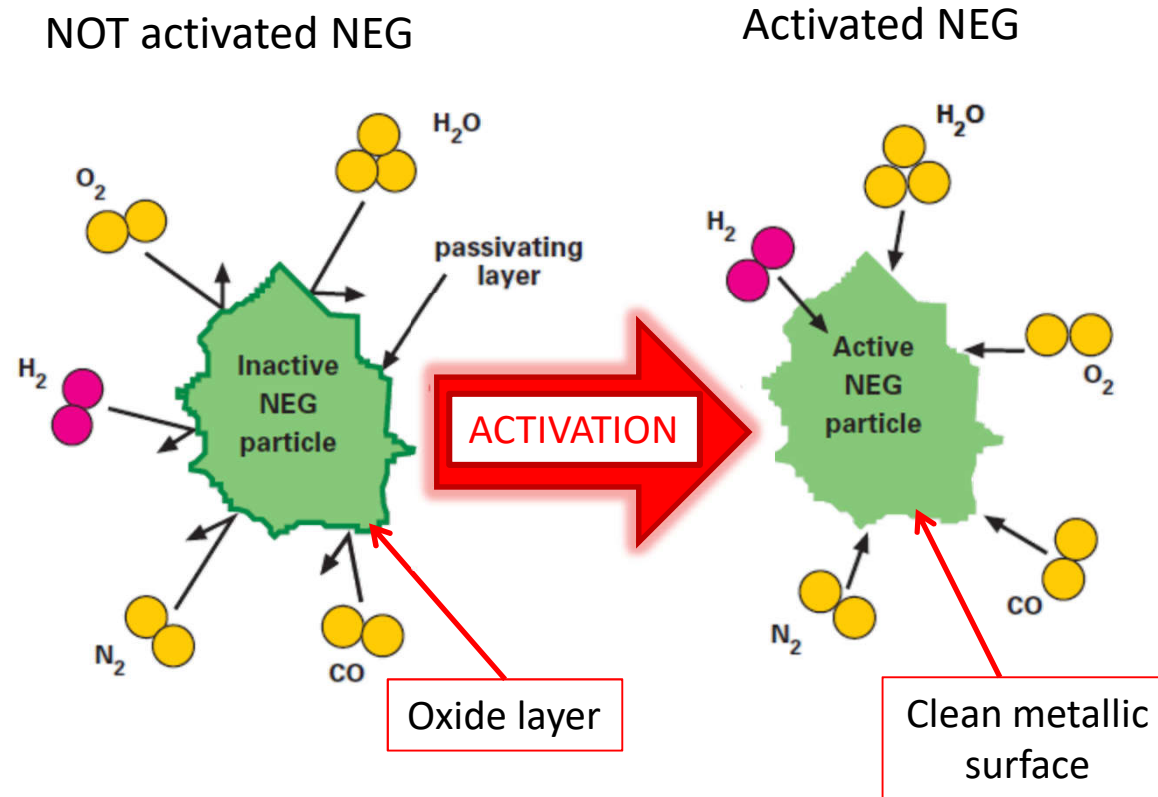
- For CO, one monolayer adsorbed,
- For O₂ several monolayers,
- For N₂ fraction of monolayer

Hydrogen diffuses in the Ti film → much higher capacity



Presented on day 3.

Non-Evaporable Getters (NEG)



Courtesy of SAES getters

On activation the oxide layer at the surface of NEG is diffused to the bulk of the material creating clean, chemically active surface where gas molecules are captured.

Non-Evaporable Getters (NEG)

NEG materials are produced industrially by powder technology. The powder is sintered to form discs or strips.

A typical alloy produced by SAES Getter is **St707** made of **Zr (70%), V (25%), Fe (5%)**.

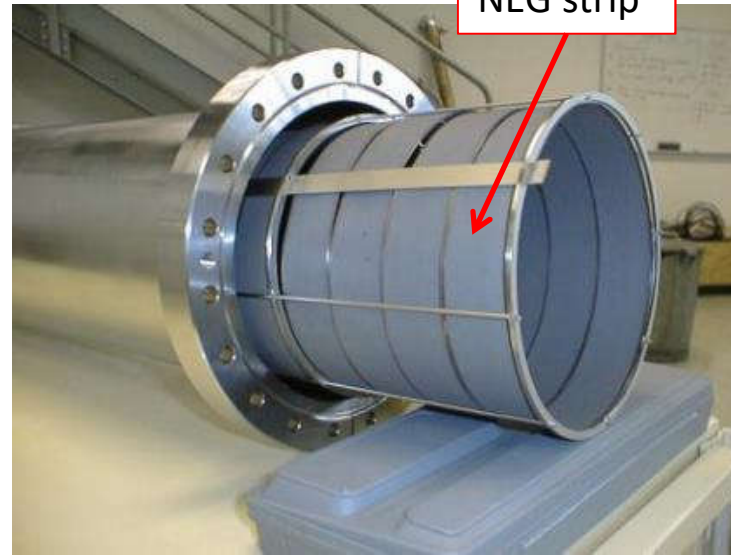
NEG strips (St707)



NEG discs St (172)



NEG strip



SAES getters

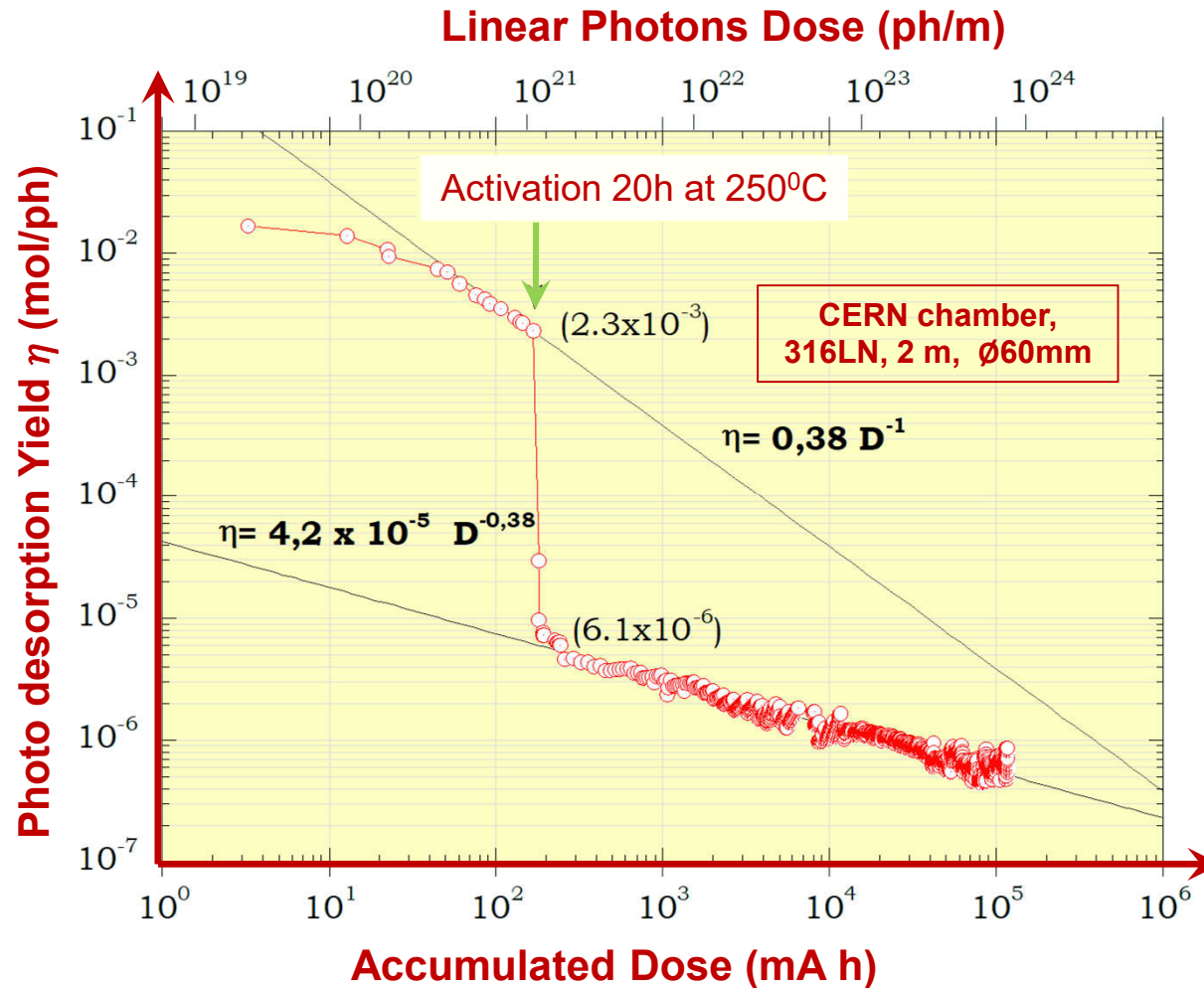
Full pumping speed is obtained after heating at 450°C for 45' or 350°C for 24h

The **high porosity of NEG materials** allows pumping of relatively high quantities of gas without reactivation. After 40 venting cycles (with nitrogen) and reactivation 80% pumping speed is conserved.

Paolo Chiggiato, Vacuum Technology for particle accelerators, 2013

NEG coatings

Photon stimulated desorption (PSD) measurements at ESRF (beamline D31).



'Synchrotron Radiation-Induced Desorption from a NEG-Coated Vacuum Chamber', P. Chiggiato, R. Kersevan